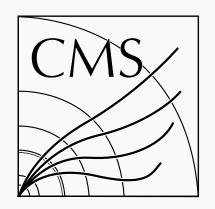


# THE CMS HGCAL DETECTOR FOR HL-LHC UPGRADE

**Artur Lobanov** LLR — École polytechnique on behalf of the CMS Collaboration







This project has received funding from the European Union's Horizon 2020 Research and Innovation programme under Grant Agreement no. 654168.



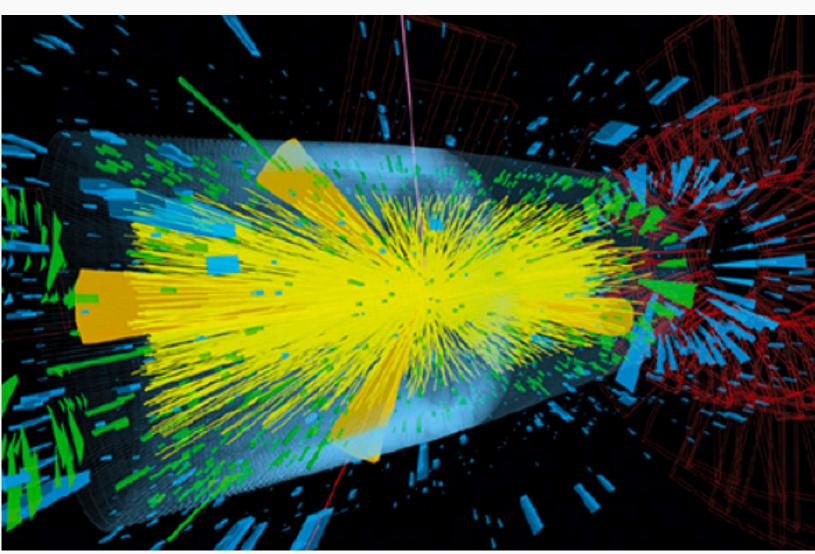




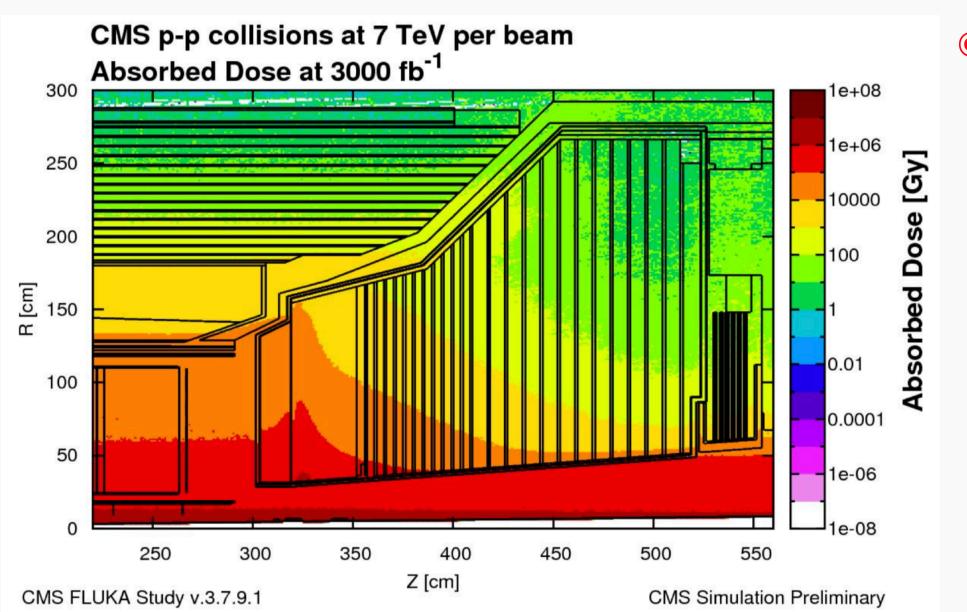




### **CMS CALORIMETER ENDCAP FOR THE HL-LHC**



• CMS Phase-2 Upgrades are required to cope with the HL-LHC demanding environment of high radiation levels and large pileup <200> PU







• Current endcap calorimeters will need to be replaced

• Preserve or even improve sensitivity in the interesting and busy forward region for VBS/VBF

• The High Granularity Calorimeter (HGCAL) will become the new Calorimeter Endcap (CE):

- Radiation hard technology based on a mix of silicon and scintillator detectors
- High transverse and longitudinal granularity + timing (5D!) for enhanced particle flow reconstruction and ID/pileup mitigation











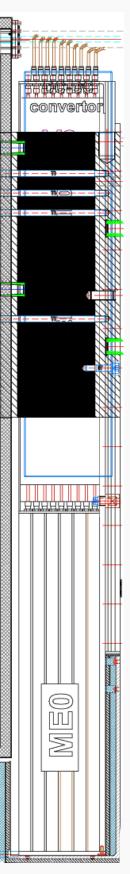
## THE CMS HIGH GRANULARITY CALORIMETER

- The high luminosity and high granularity are a big challenge for the detector design:
  - Silicon/scintillator detectors in the high/low radiation regions 28 layers in the ECAL (CE-E) + 24 layers in the HCAL (CE-H) compartments Triggering and reading data of >6M channels at 40 MHz illator  $m^2$ CE-E  $\mathbf{00}$ CE-H (Si) (Si) 0 cm<sup>2</sup> 000

Endcap coverage: $1.5 <  \eta  < 3.0$		
Total	Silicon sensors	Scinti
Area	600 m <sup>2</sup>	500
Number of modules	27 000	4 0
Cell size	0.5 — 1 cm <sup>2</sup>	4 — 3
N of channels	6 000 000	400
Power	Total at end of HL-L ~180 kW @ -30°C	



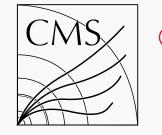




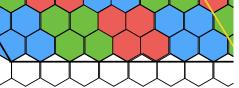


## **KEY INGREDIENTS OF HGCA**

- Active elements:
  - 8" hexagonal silicon wafers p/n-type | thickness: 120/200/300 um | 192/432 cells | HV bias up to 1kV
  - SiPM-on-tile scintillator readout (à la CALICE AHCAL)
- Electronics:
  - Front-End ASIC: rad. hard | low noise | high dynamic range (1-1000 MIP) timing measurement | < 15 mW/ch consumption</li>
     Silicon sensors
    - High range with low power due to time-over-threshold (TOT)
    - Time-of-arrival (TOA) method with time precision of 20 ps
  - Trigger data from ASICs (300 TB/s) fed through concentrators to the back-end system (2 TB/s) in multi-stage approach
- Engineering:
  - 30°/60° cassettes tiled with hexagonal silicon modules and partially mixed with scintillator tile boards

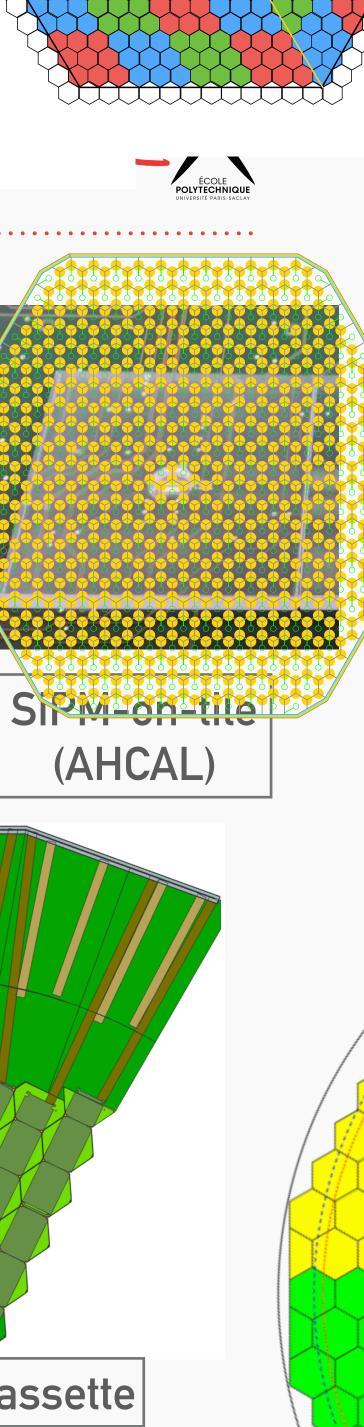


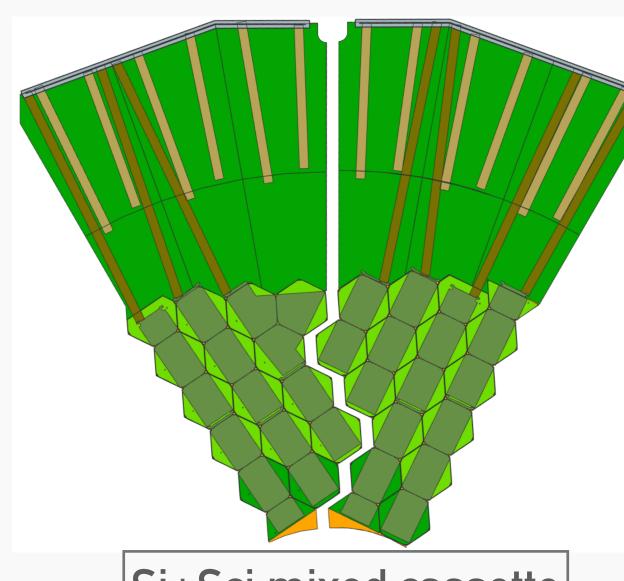
• Full detector volume cooled to -30°C





192 cells 432 cells





### Si+Sci mixed cassette

# PHYSICS PERFORMANCE







••••

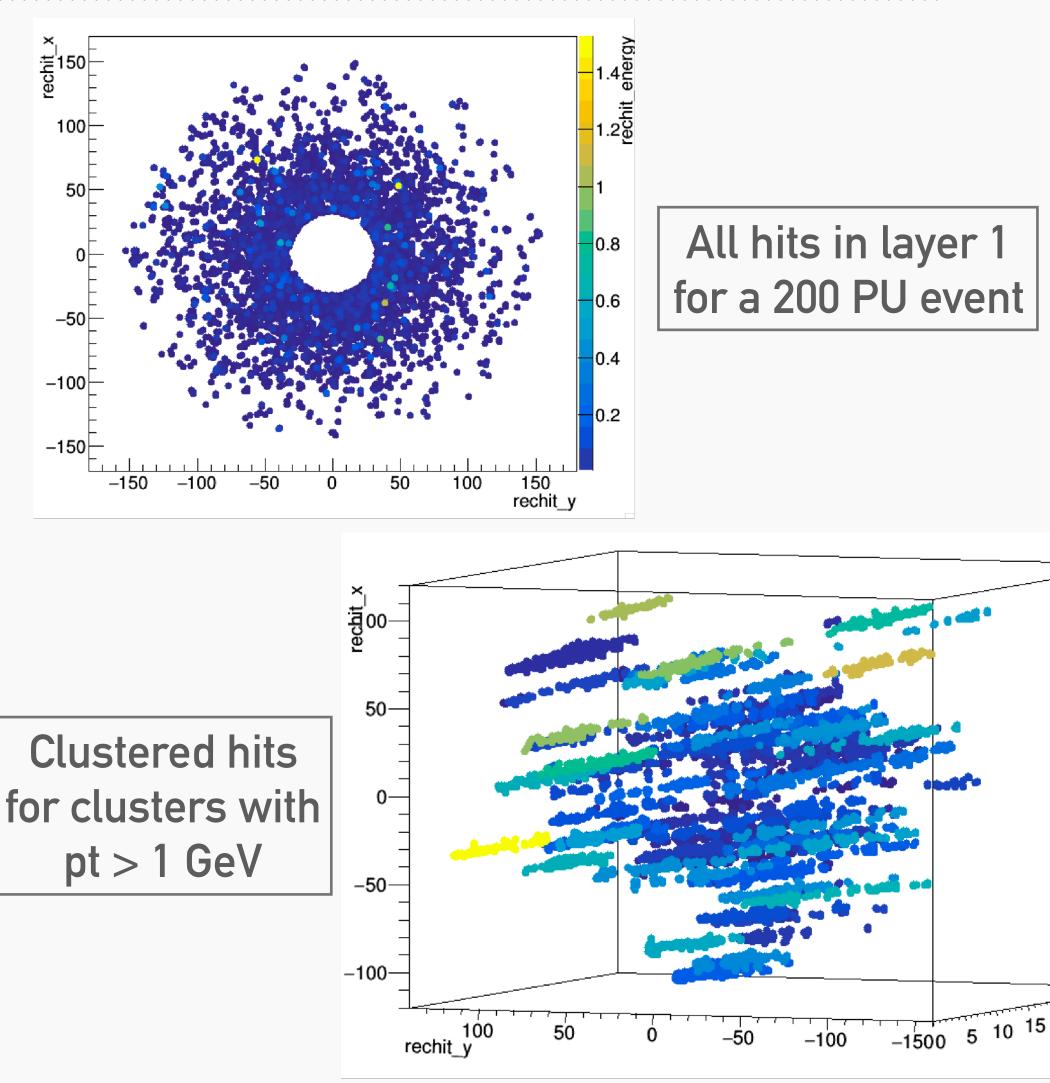
## **PHYSICS PERFORMANCE**

- The high occupancy and pileup are both big challenges for the particle reconstruction
  - But HGCAL is an 5D imaging calorimeter:
    3D position, energy and time
    - Ultimate detector to perform Particle Flow
- The very first step is the clustering of the hits. Currently, the clustering is done in two steps:
  - 2D clustering in every layer using an energy density-based imaging algorithm
  - 3D clustering in an IP-pointing cylinder
- Great opportunity for novel tracking, clustering and imaging techniques as DBSCAN and CNNs!





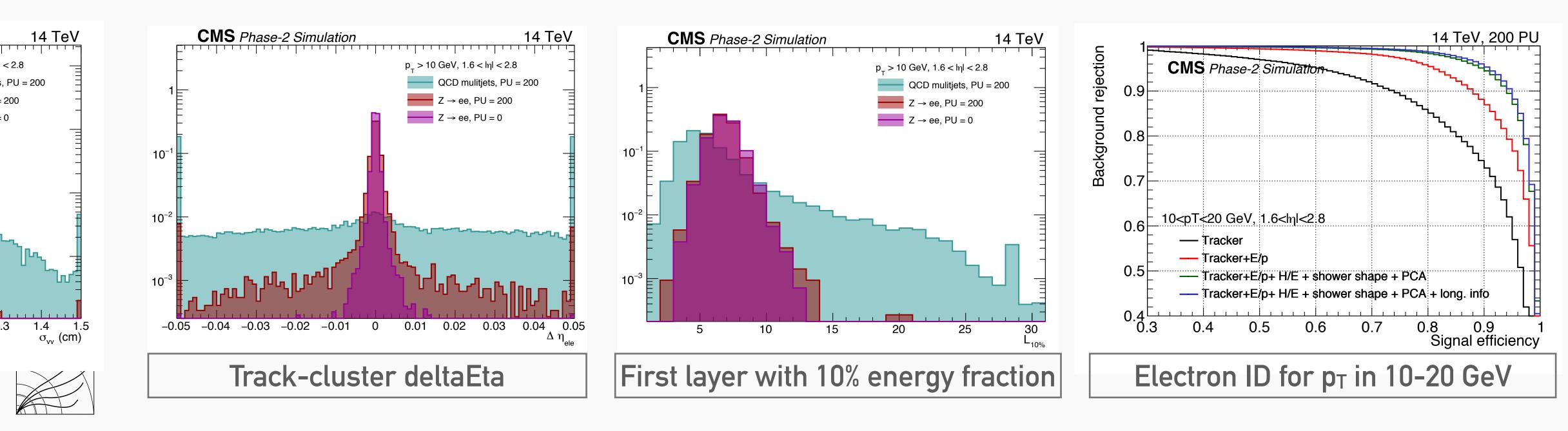
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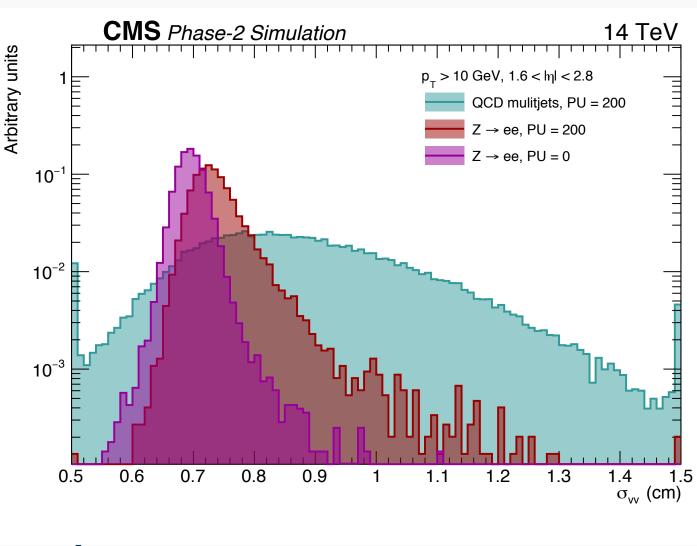




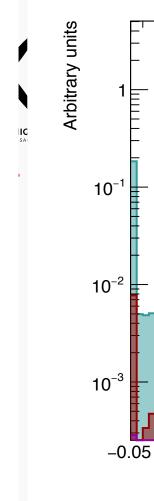
## **ELECTRON IDENTIFICATION**

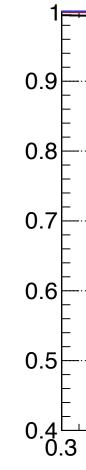
- Electrons are a 'standard candle' for Particle Flow: EM showers are compact (R<sub>Moliere</sub> ~ 3 cm), of known shape
  - 3D information allows reconstruction of the shower ax Component Analysis) and the measurement of shower unprecedented precision





### Axis pointing improves rejection of PU photons with respect to bremsstrahlung

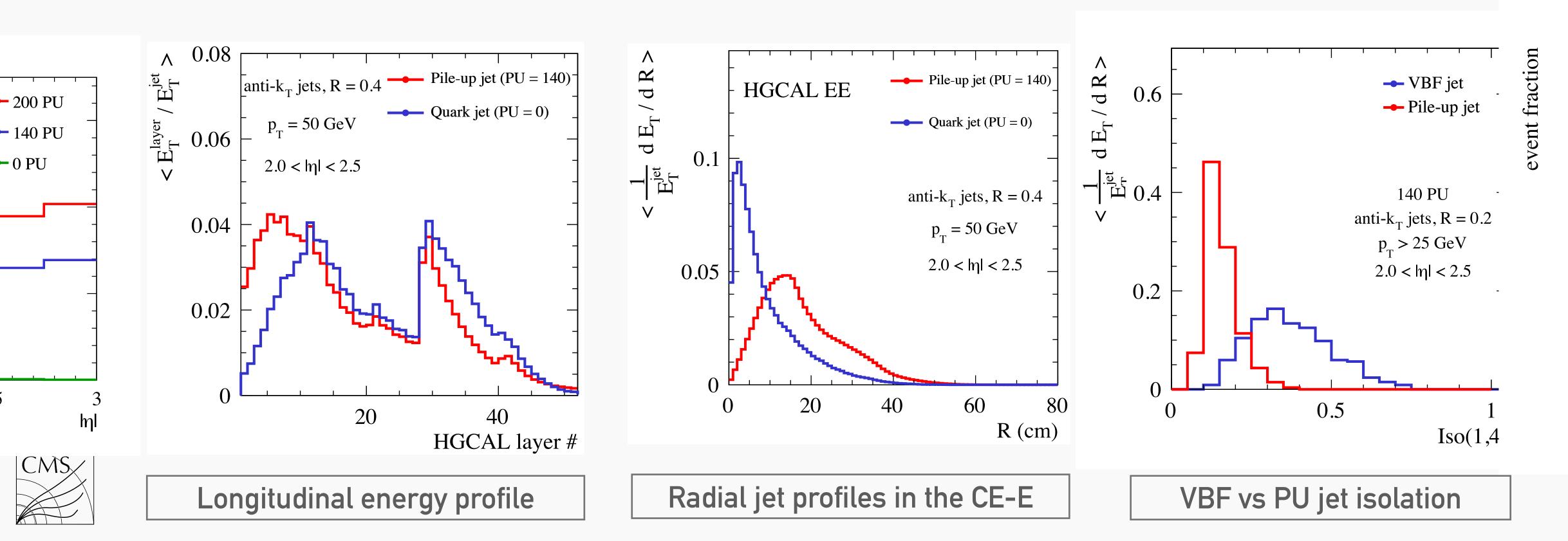


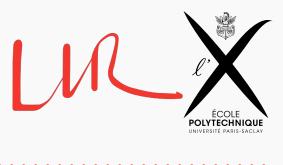




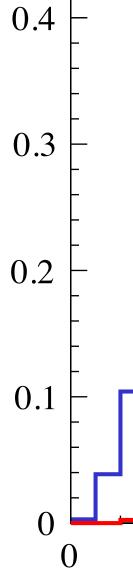
### **JET IDENTIFICATION**

- - Pileup jets start to develop earlier in the calorimeter and are wider
  - Promising for resolving boosted topologies as VBF jets, top tagging, etc.





• The high granularity allows for the separation of pileup jets with shape variables













# BEAM TESTS



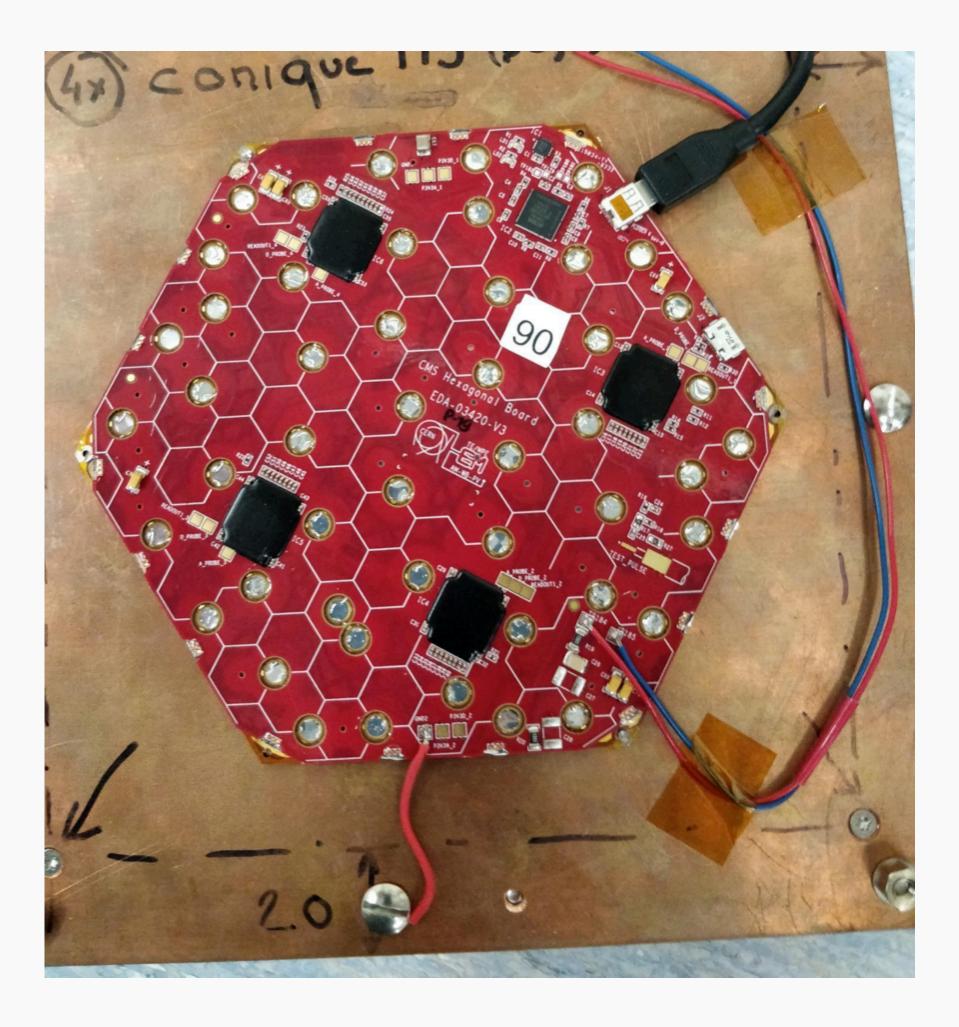
### **BEAM TESTS**

- Several beam tests performed in 2016-2018
- Main objectives for beam tests:
  - Physics performance of the CE-E and CE-H silicon / scintillator parts

  - Verification of the MC simulation Validation of basic FE ASIC architecture in beam conditions: TOT and TOA
  - Technological prototyping of the detector modules
  - System test development in parallel





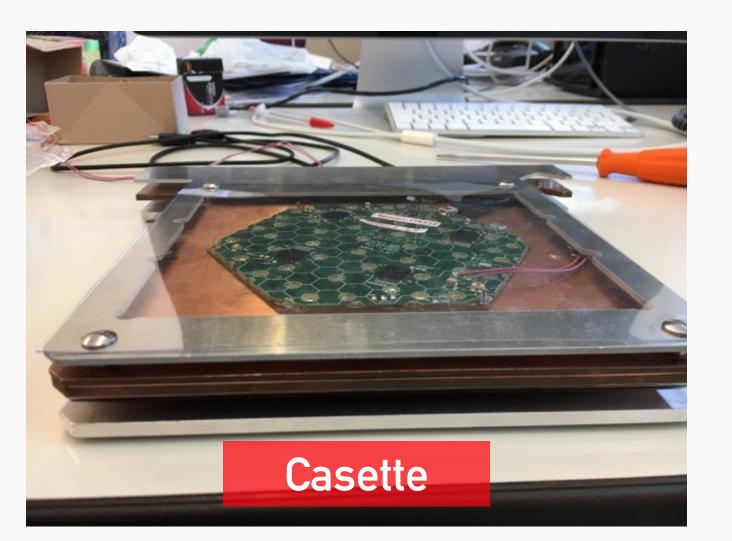


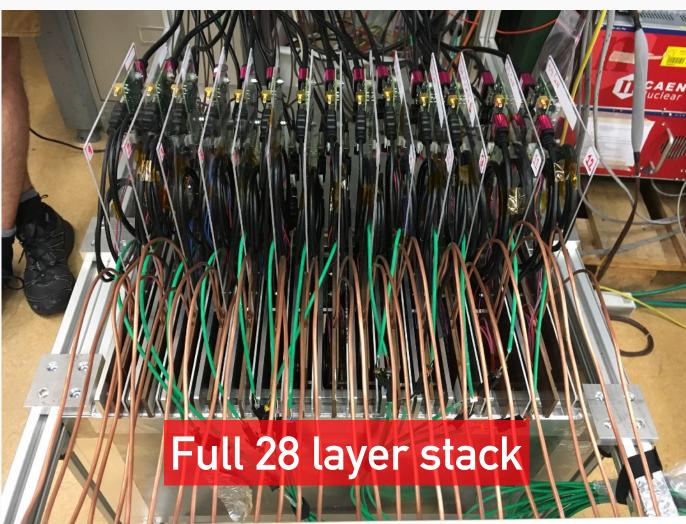
6" hexagonal silicon module prototype



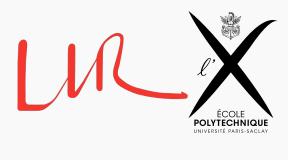
### **RECENT TEST BEAMS**

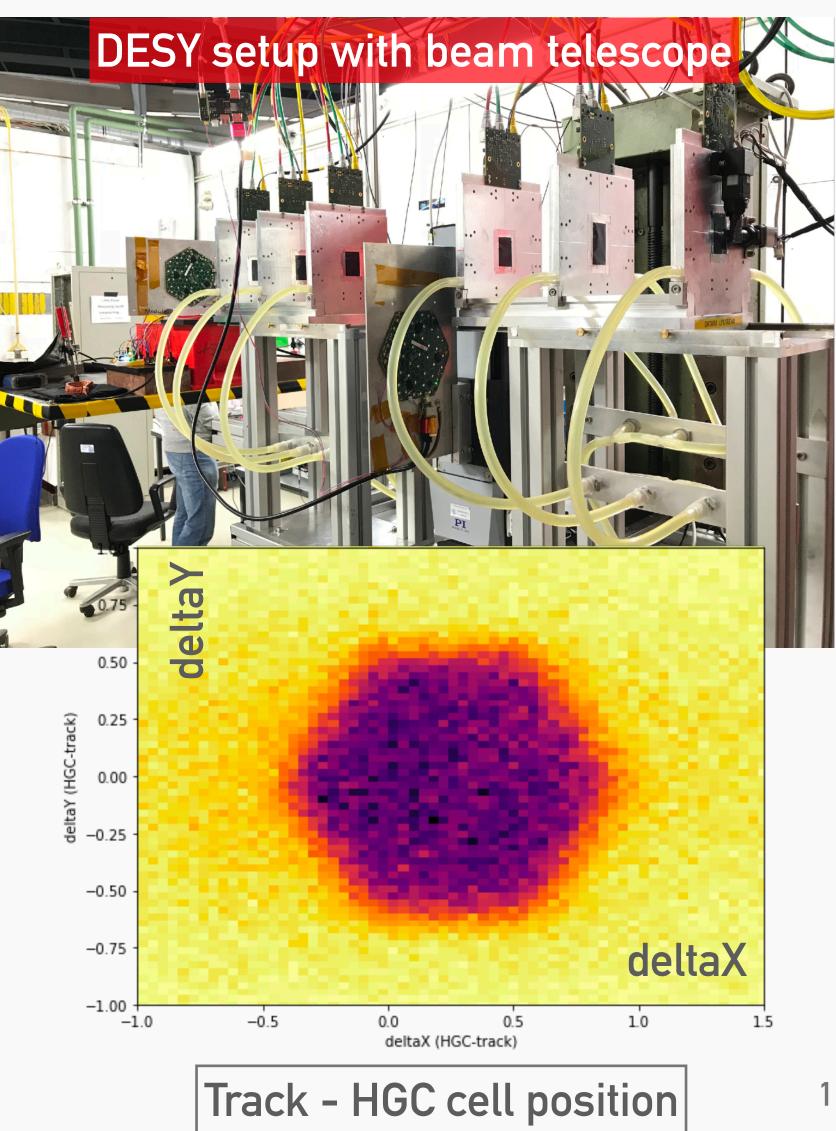
- DESY: March 2018
  - Studies of single module response using low energy electrons (1-6 GeV) as MIPs and in showers
  - AIDA beam telescope for precision tracking ( $\sigma_{xv} \sim 10 \ \mu m$ )
- CERN: June 2018
  - Full CE-E depth prototype with 28 modules arranged in double-sided cassettes with integrated cooling
  - Studies of electrons (and pions) in with E = 10-150 GeV





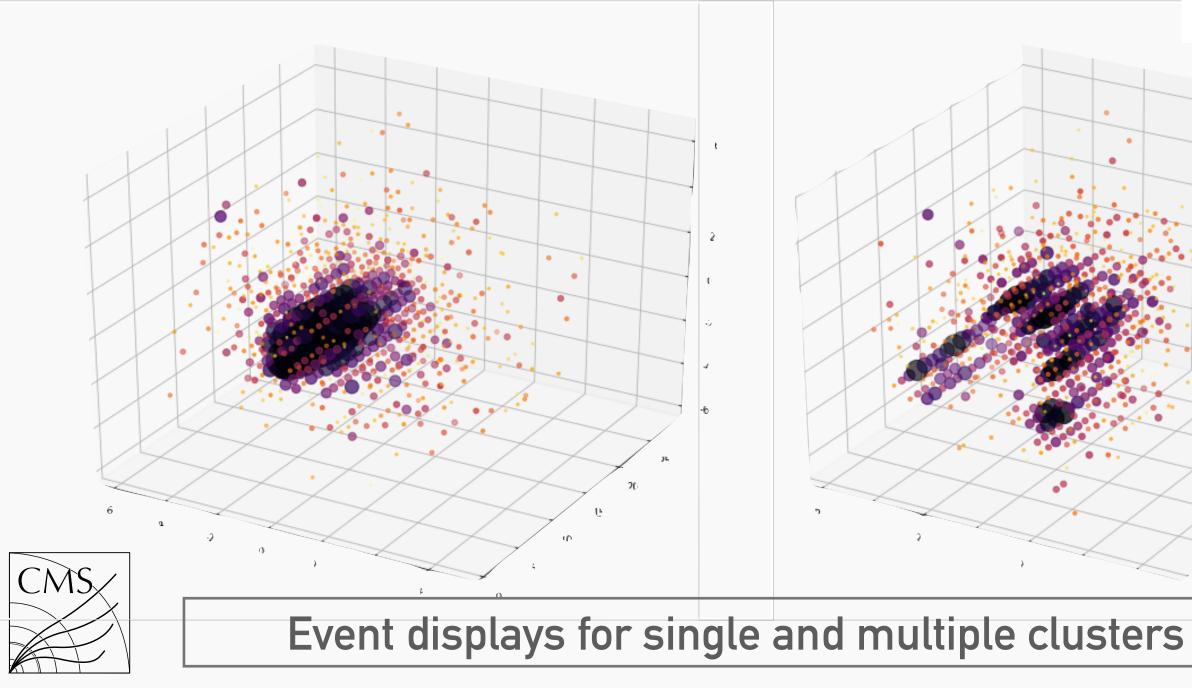




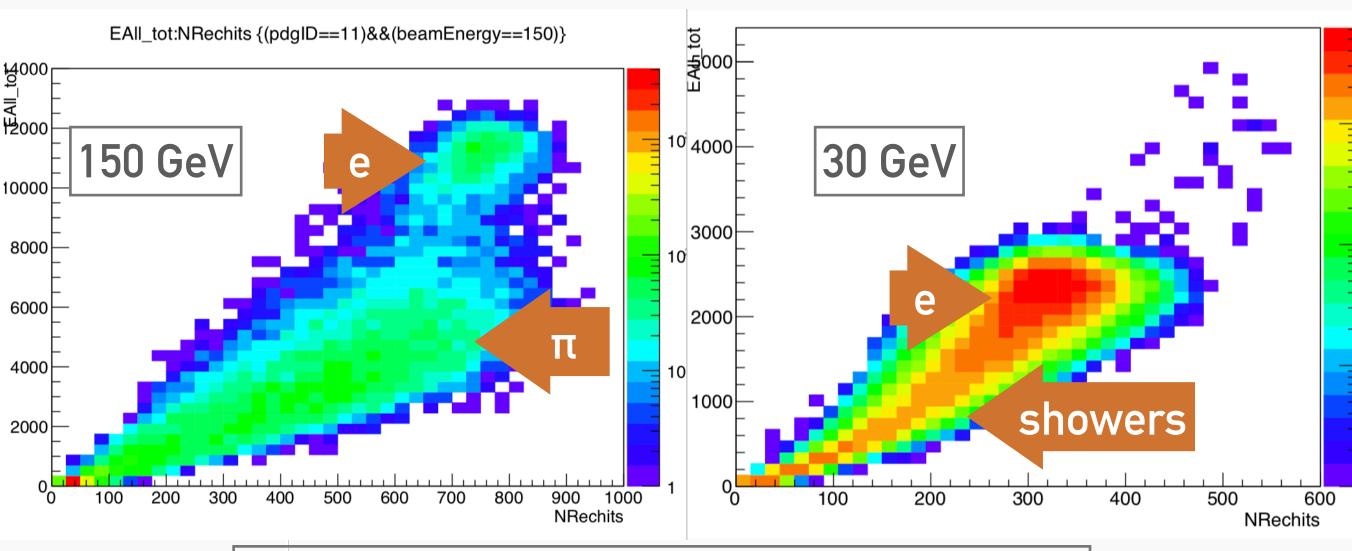


## **CERN BEAM TEST IN JUNE 2018**

- Significant  $\pi$  contamination of electron beam at high energies [expected]
  - 99% purity < 80 GeV; <10% for 150 GeV
  - Consistent with simulated e/pi mix
  - Studying mitigation by ID variables



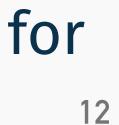




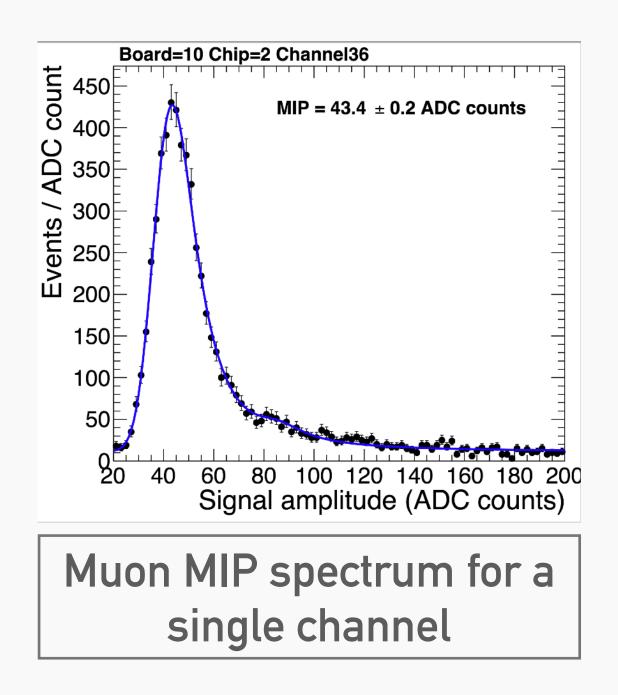
Total uncalibrated energy vs number of hits

- Early showering electrons [unexpected]
  - Requires cleaning of data and limits statistics for E measurement,
  - ... but provides interesting data for pattern recognition/clustering!



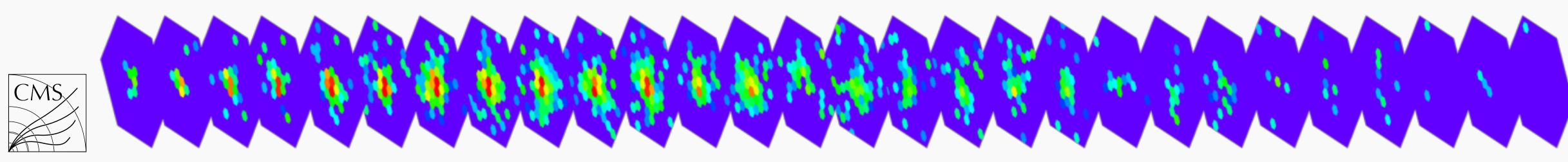


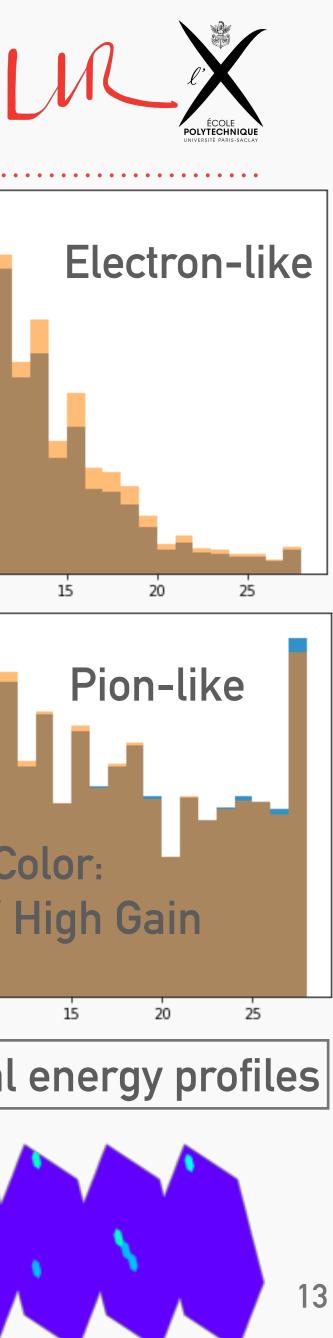
## **CERN BEAM TEST IN JUNE 2018**

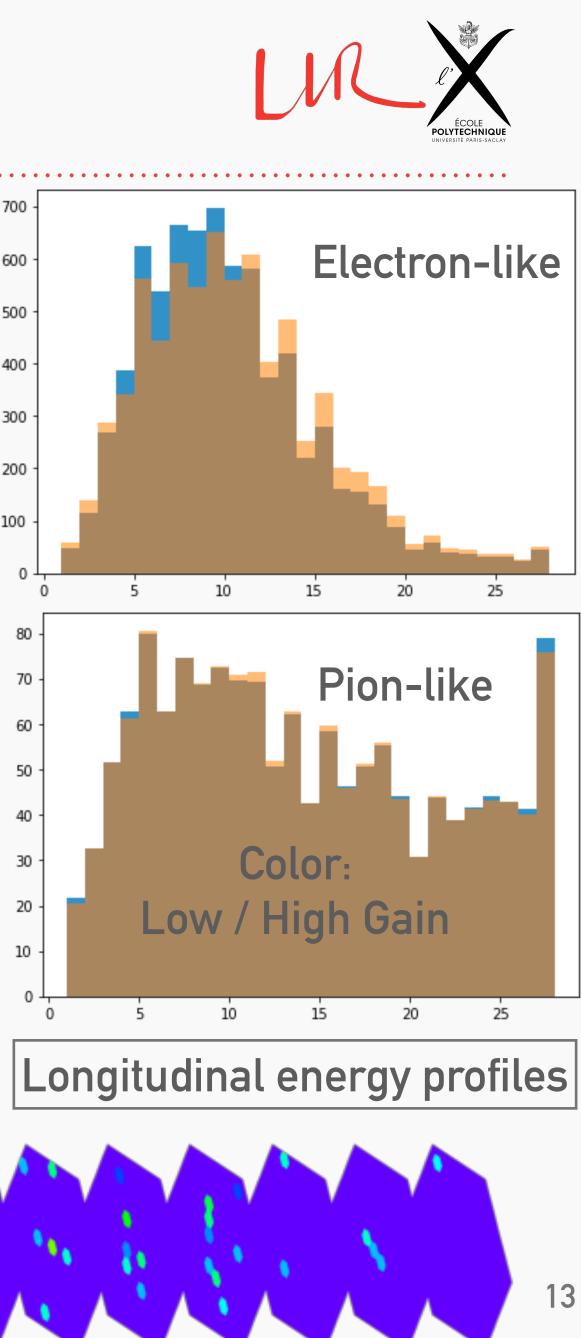


- Preliminary results:
  - Clean MIP spectra for calibration
  - Longitudinal shower shapes distinguishable for electrons/pions
  - Energy reconstruction works well even with preliminary calibration
  - Basic agreement with Geant4 simulation for energy and multiplicity

Event display for an 80 GeV electron

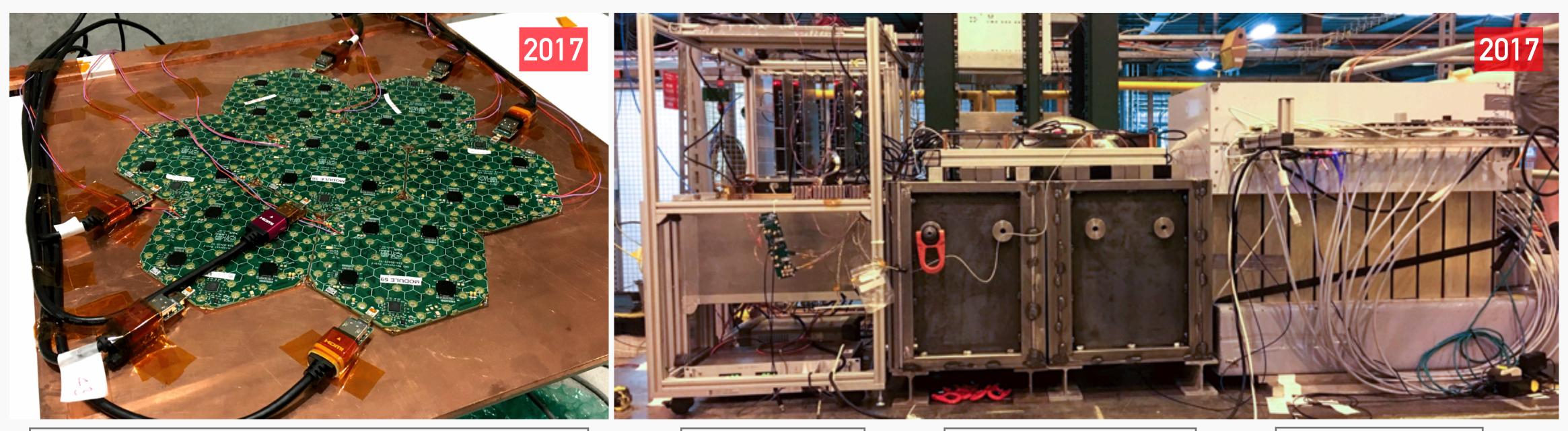






## **ONGOING ACTIVITIES TOWARDS OCTOBER 2018 TB**

- Next CERN beam test in October 2018:
  - Silicon: CE-E + 12 layer CE-H (7 modules/layer) | Scintillator: CALICE AHCAL
  - Setup as in 2017, but with ~100 modules in total vs. 20 in 2017
  - Aiming at exploiting the full potential of the test system (including timing)





**CE-H plate with 7 modules** 





**CE-H** stack









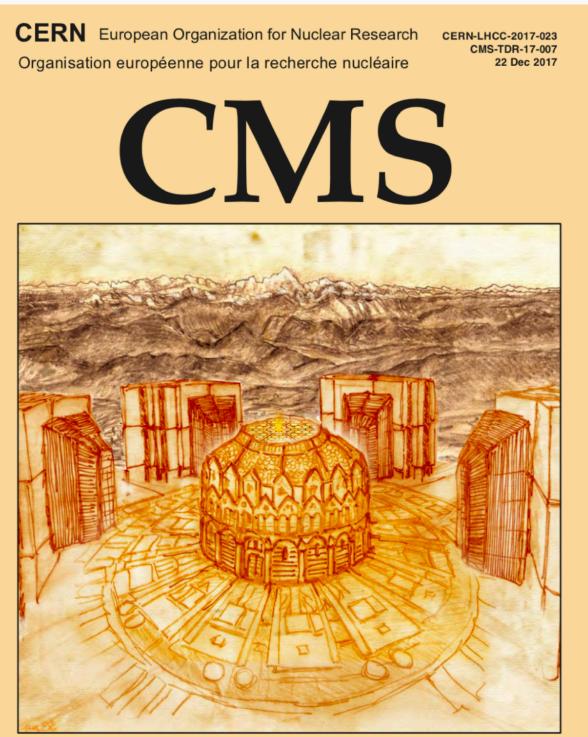


# SUMMARY



### SUMMARY

- CMS High Granularity Calorimeter is a very challenging detector
  - Harsh radiation environment, high pileup & occupancy
  - Large number of channels, low noise, large dynamic range, high speed, low power ...

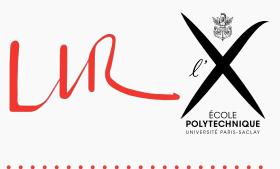




- 5D (3D position + energy + time) measurement of showers provides unique opportunities in particle reconstruction for identification and pileup mitigation
- Ongoing test beam campaign to validate technology and physics performance
- Engineering Design Review to review full design scheduled for mid 2020



The Phase-2 Upgrade of the **CMS Endcap Calorimeter Technical Design Report** 



• TDR approved in April 2018: cds.cern.ch/record/2293646















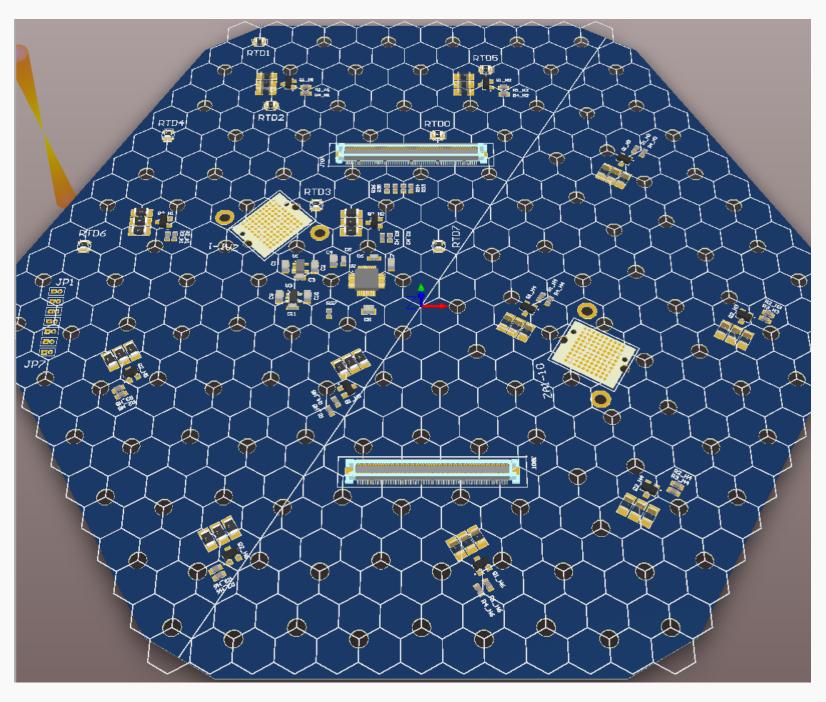
# BACKUP

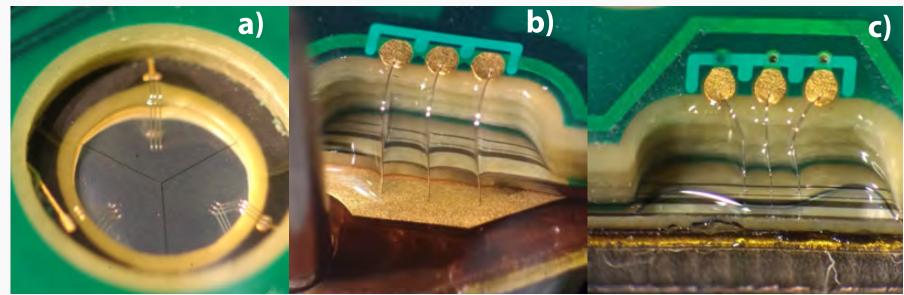


## **FRONT-END ELECTRONICS**

- Detector modules with 2 PCBs < 6mm thick:
  - 1. PCB: "hexaboard" Wire-bonds to Si-sensor and very-FE ASICs
  - 2. PCB: Motherboard for powering, data concentration, trigger generation and bi-directional communication
- Trigger/data transfer: low-power GBT links (lpGBT)







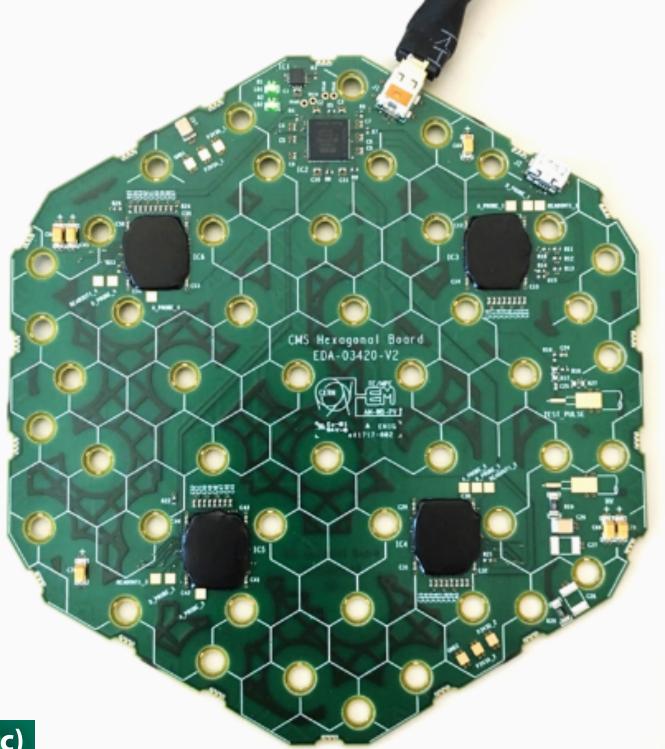






### Hexaboard design for HGCROC

### Hexaboard PCB for Test Beam

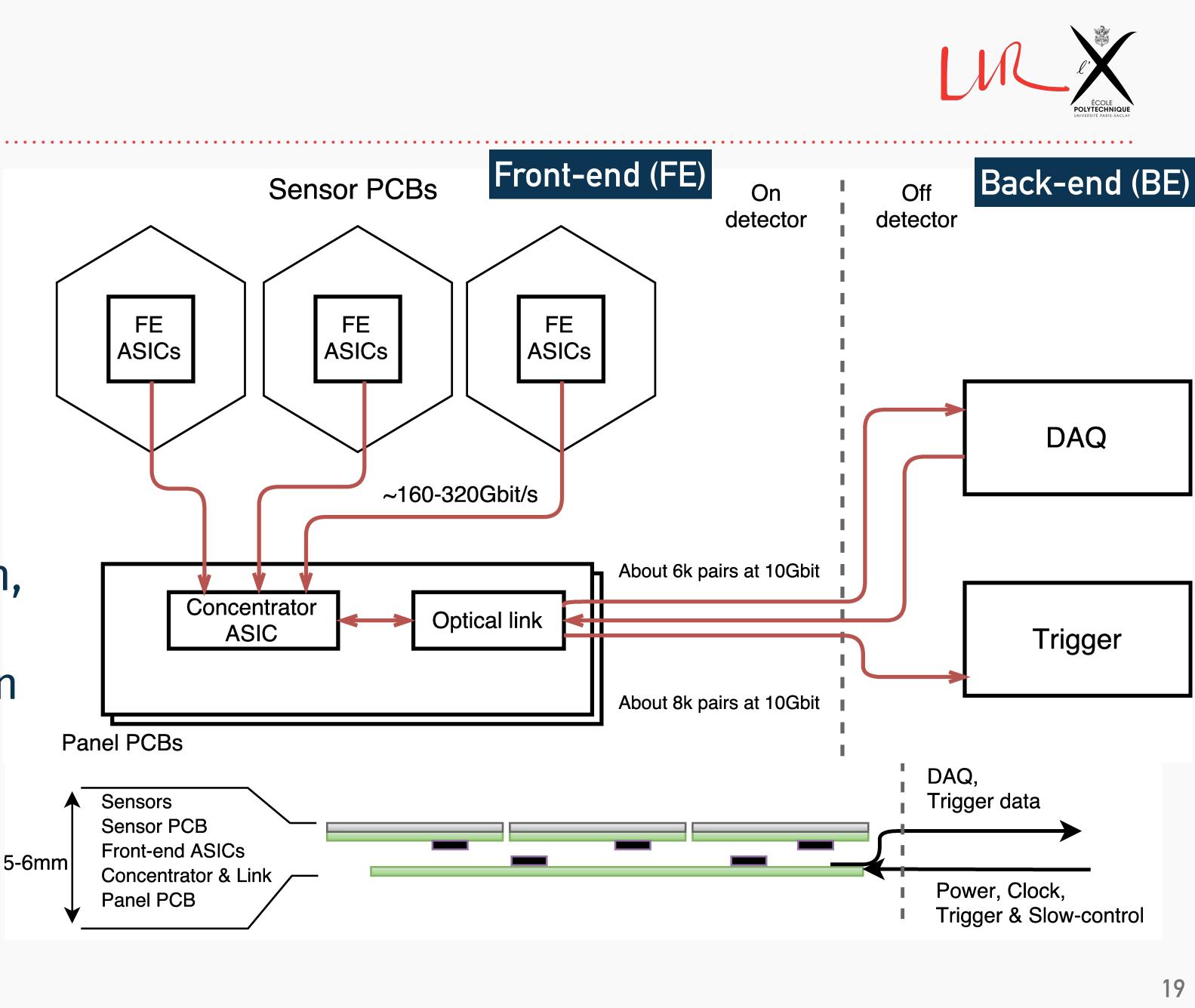


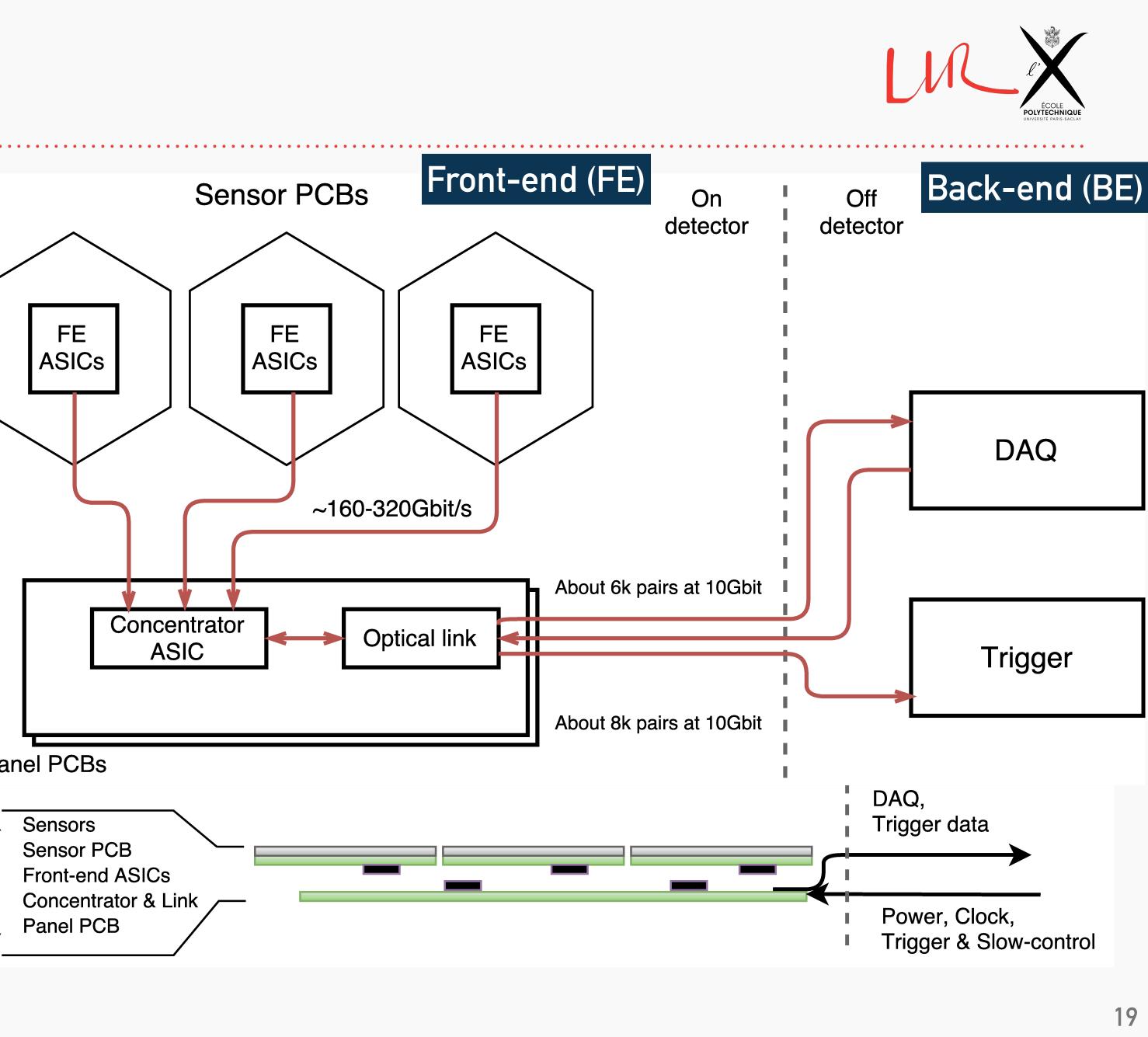
### Wire-bonds from Silicon to 1. PCB



## **FRONT-END ELECTRONICS**

- Detector modules with 2 PCBs < 6mm thick:
  - 1. PCB: "hexaboard" Wire-bonds to Si-sensor and very-FE ASICs
  - 2. PCB: Motherboard for powering, data concentration, trigger generation and bi-directional communication
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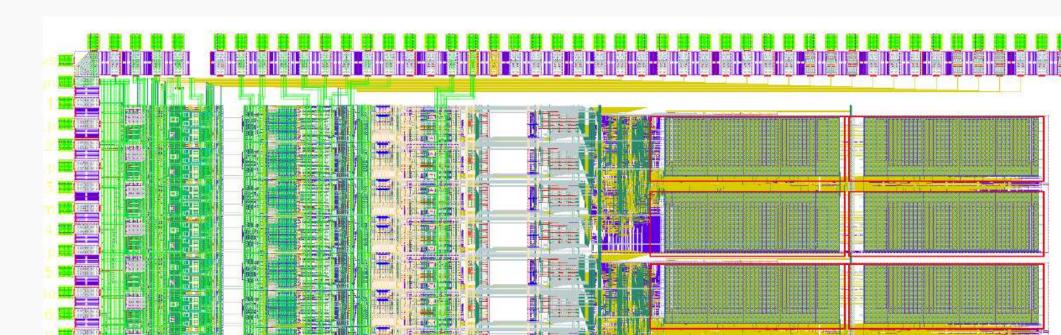


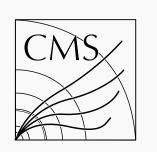


### **VERY FRONT-END ASIC**

- At the heart of the detector electronics is the front-end readout ASIC
- The design and environment of the HGCAL pose several requirements
  - System on chip: charge, time, digitization, data and trigger processing, ZS ...

- Low power: < 15 W/channel</p>
- Low noise: < 2000 e<sup>-</sup>
- High radiation: 10<sup>16</sup> n<sub>eq</sub> (1MeV eq.)/cm<sup>2</sup>
- High speed readout: > 1 Gb/s
- Same ROC for Si&SiPM





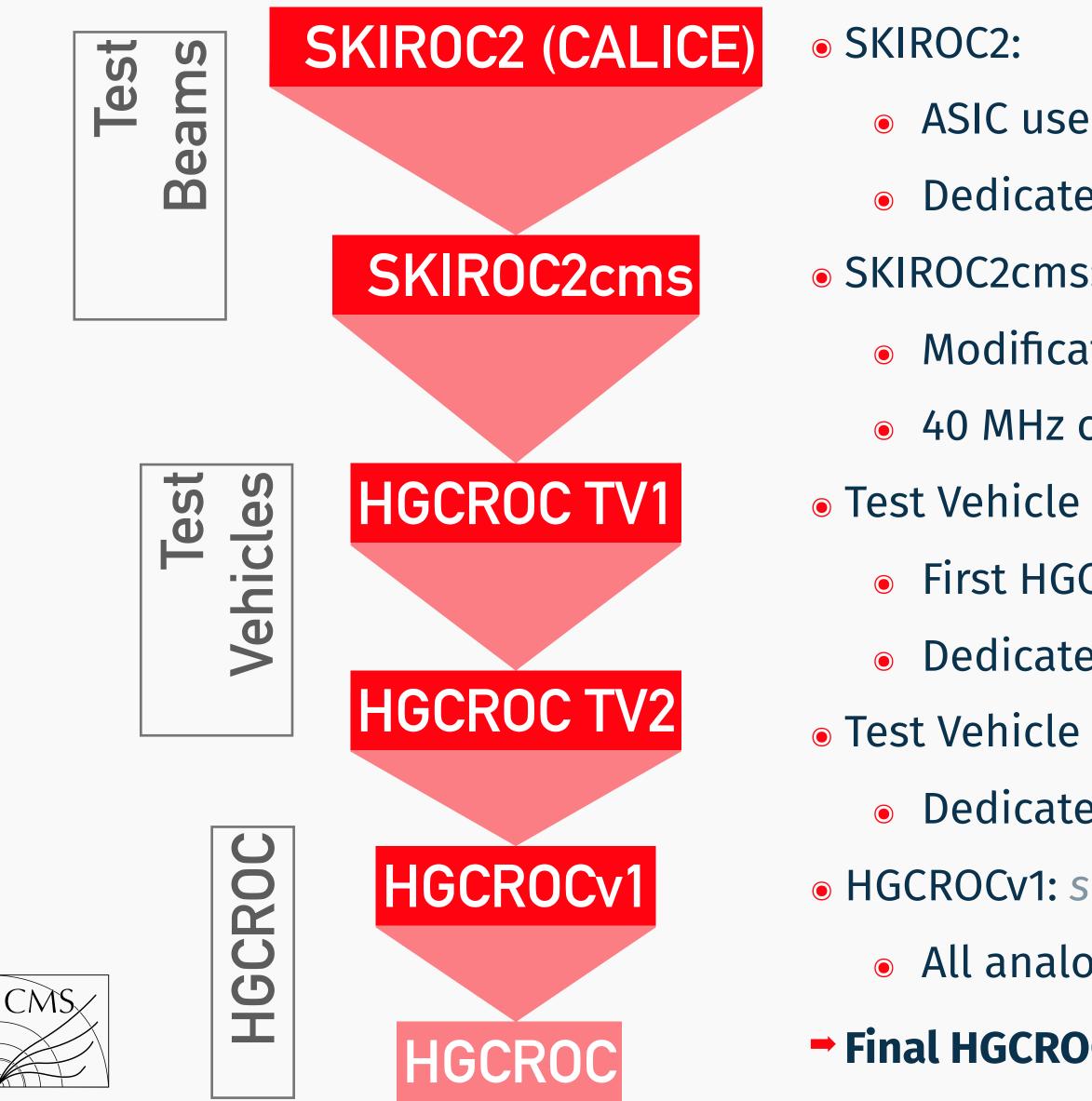


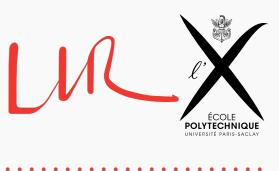
- Signal: high dynamic range: 0–10 pC
  - Charge: 0–100 fC [11 bits]
  - Time over Threshold: 0.1–10 pC [12 bits]
  - Timing information: Time of Arrival with 25 ps resolution > 50 fC [12 bits]





## HGCAL ASIC EVOLUTION: FROM SKIROC TO HGCROC





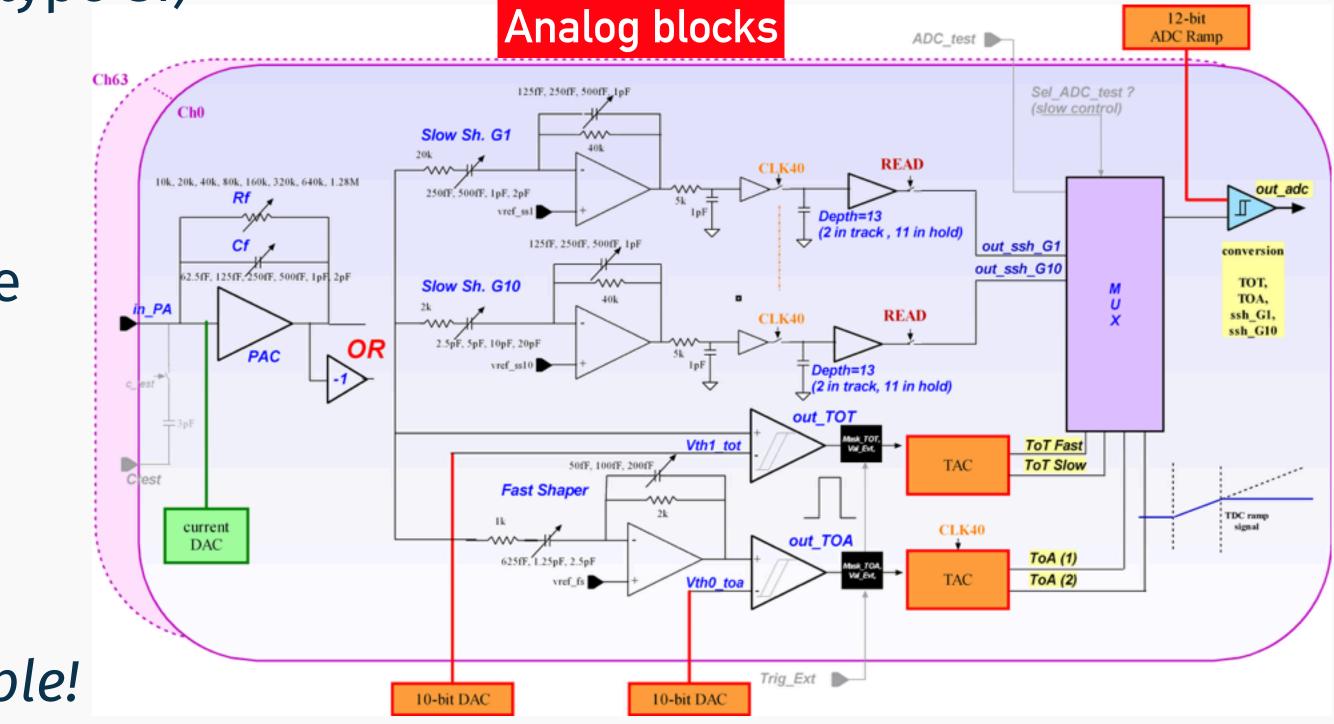
- ASIC used by CALICE in the SiW ECAL
  - Dedicated 64 channel Si-detector readout ASIC, SiGe 350 nm
- SKIROC2cms: submitted and received in 1Q of 2016
  - Modification for test beams with CMS-like running conditions
  - 40 MHz clock and sampling, Gain + ToA + ToT
- Test Vehicle 1: submitted in May 2016, received in August 2016
  - First HGCROC test vehicle in CMOS 130 nm architecture
  - Dedicated to preamplifier studies
- Test Vehicle 2: submitted in December 2016, received in May 2017
  - Dedicated to analog channel study for TDR
- HGCROCv1: submitted in July 2017, expected in October 2017
  - All analog and mixed blocks; many simplified digital blocks
- Final HGCROC submission by mid 2019!

## SKIROC2CMS: ASIC FOR BEAM TESTS [Q1 2016]

- Modified 64ch CALICE SKIROC2 specially for test beam use
- Dual polarity preamplifier (for p- or n-type Si)
- 40 MHz clock and 25 ns sampling
- ADC: low and high (x10) gain
  - Slow shaper with 40ns shaping time
  - 300ns in rolling analog memory
- Time-of-Arrival proof of principle!
  - Fast shaper (5 ns)
- Time-over-Threshold proof of principle!
  - For large signals directly from the preamplifier
- TDC (TAC) for TOA & TOT (~20 ps binning, ~50ps jitter)

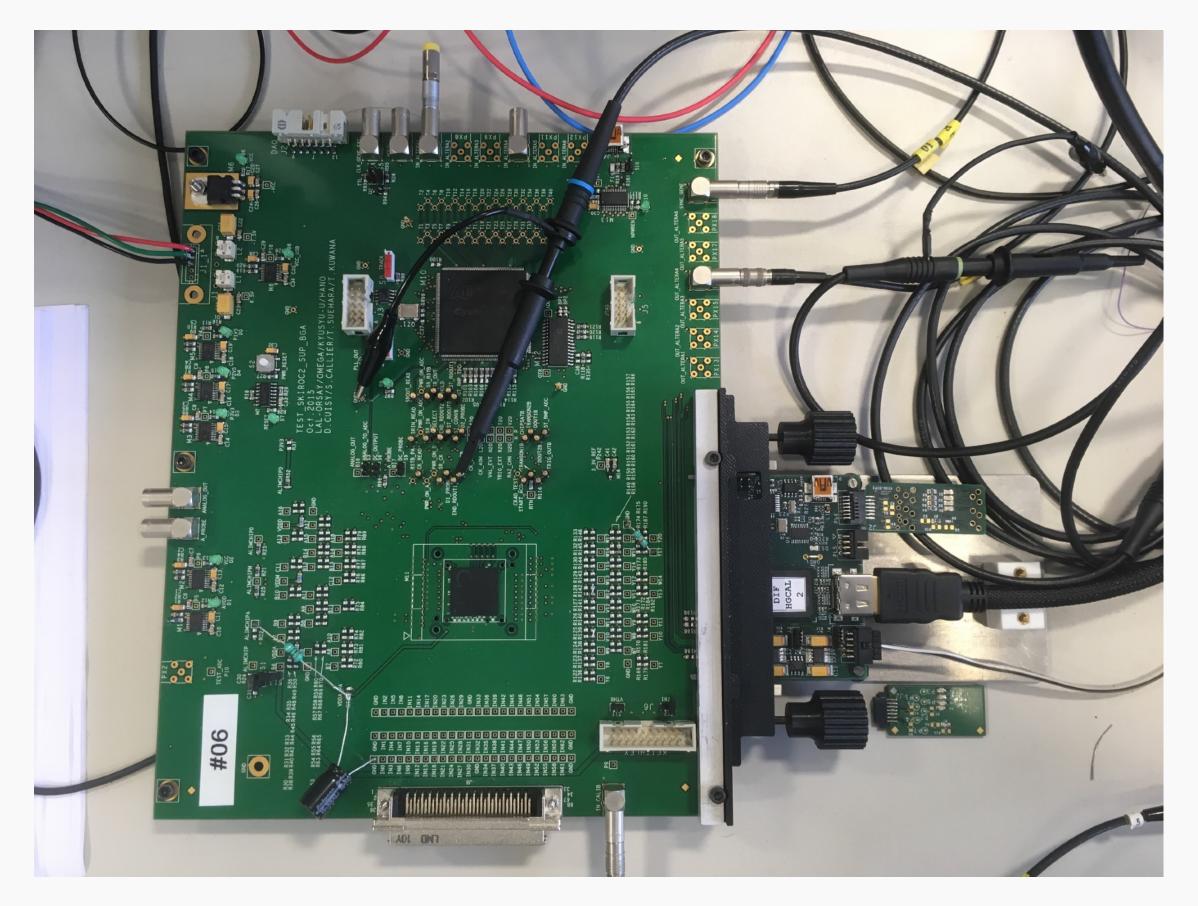






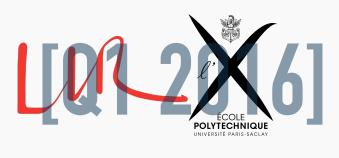


### **SKIROC2CMS: ASIC FOR BEAM TESTS**



### ASIC test board





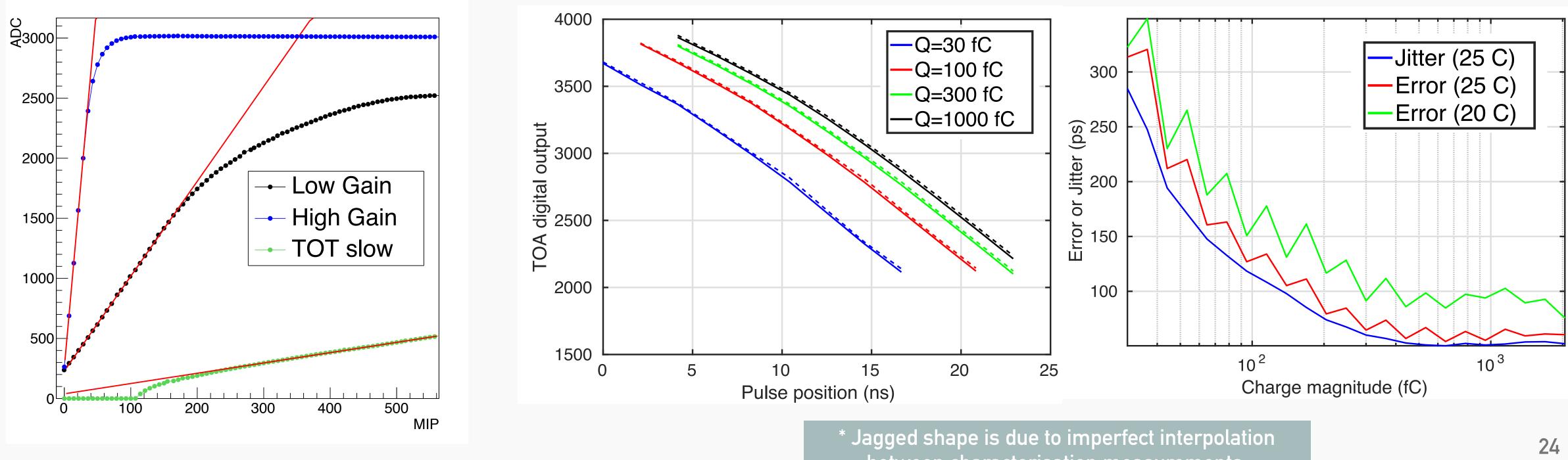
- Extensive tests of the SKIROC2cms ASIC have been performed
  - Gain and TOT linearity, noise, pedestals
  - TOA transfer characteristics, efficiency, time-walk, jitter
  - Temperature stability
- On single-ASIC test board and hexaboard
- More details about the TB performance in tomorrow's talk by Thorben Quast



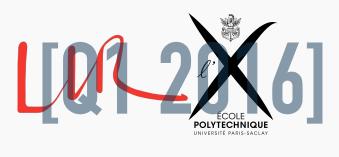


## **SKIROC2CMS: ASIC FOR BEAM TESTS**

- ADC and TOT linearity:
  - HG/LG linear until 500 fC
  - TOT linear for 500fC 10pC
- Noise for gain: ~ 3500 e<sup>-</sup>







- TOA performance:
  - Off-line correction for time-walk possible
  - Constant term: 50 ps
  - Noise term: 10ns/Q(fC) [expected ~4ns/Q]

between characterisation measurements.

## **TEST VEHICLES FOR HGCR**

- CMOS 130 nm: rad hard technology
- 6 positive + 6 negative input preamplifiers
- 1 baseline channel
- 4 discriminators for TOT
- CR-RC shapers: HG and LG
- Digital part for noise couplir

Building blocks successfally tested Noise in TV2 as in specification tion

TV1

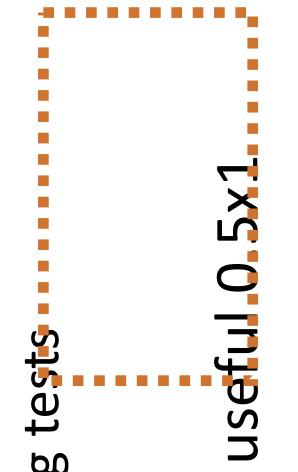




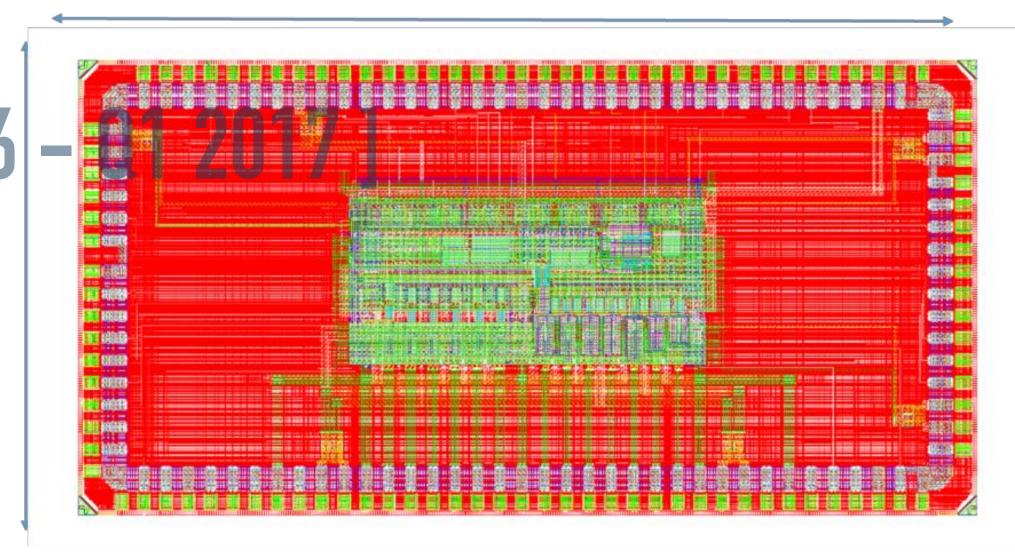
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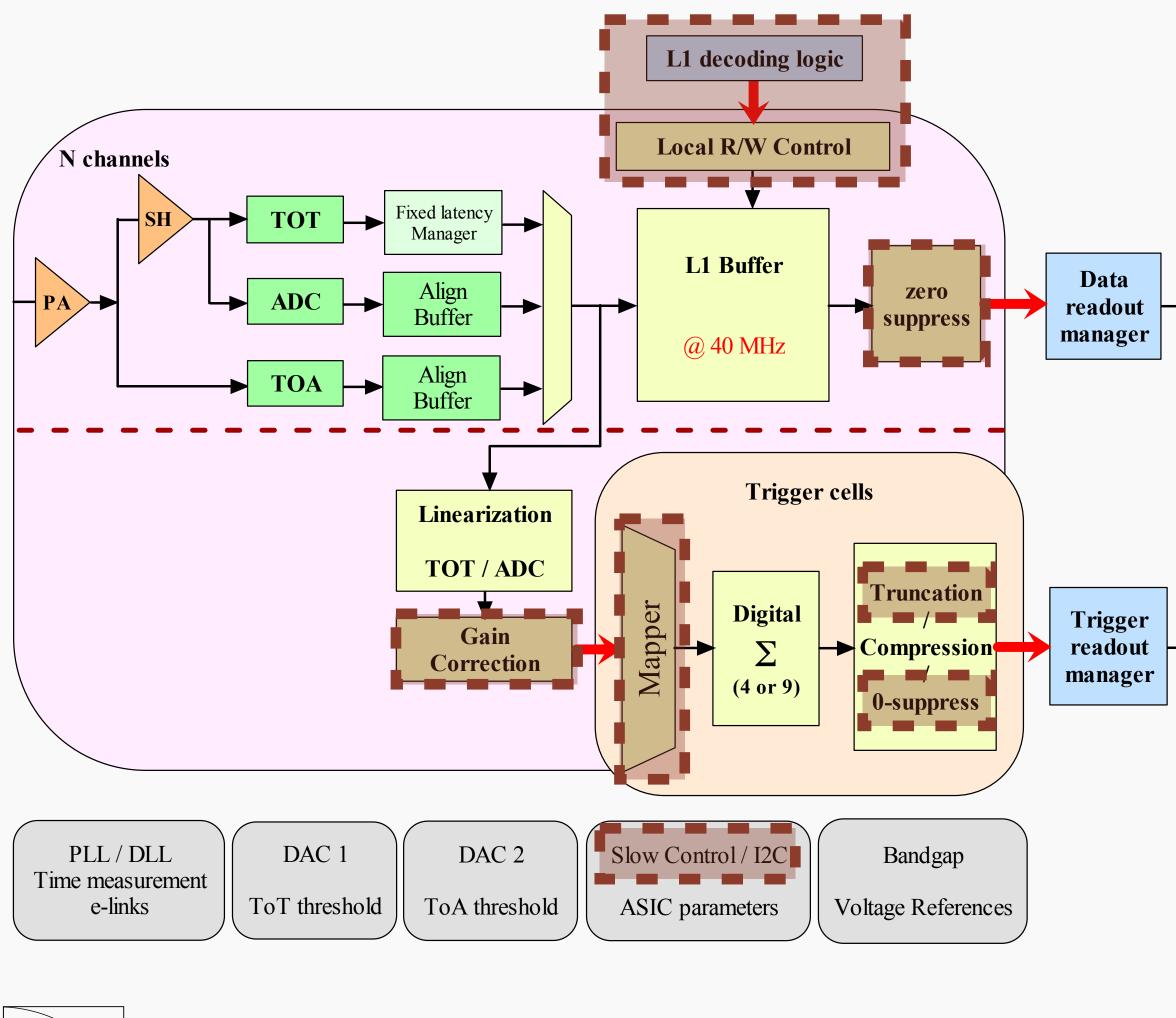


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## HGCROCv1 [Q3 2017]



\*Not yet included





- 32 channels for development/cost
- Dual polarity (for p- or n-type silicon)
- TOA, TOT with 2 variants: low power or DLL
- I1-bit SAR ADC @ 40MHz
  - Simplified Trigger path: no ZS, only 4 sums
  - Data readout @ 320MHz
- Trigger

Data

- Slow Control with triple voting (shift register like SK2-CMS)
- Digital blocks with simplified architecture
- Services: bandgap, PLL, 10b DAC
- No interface to GBT/concentrator yet



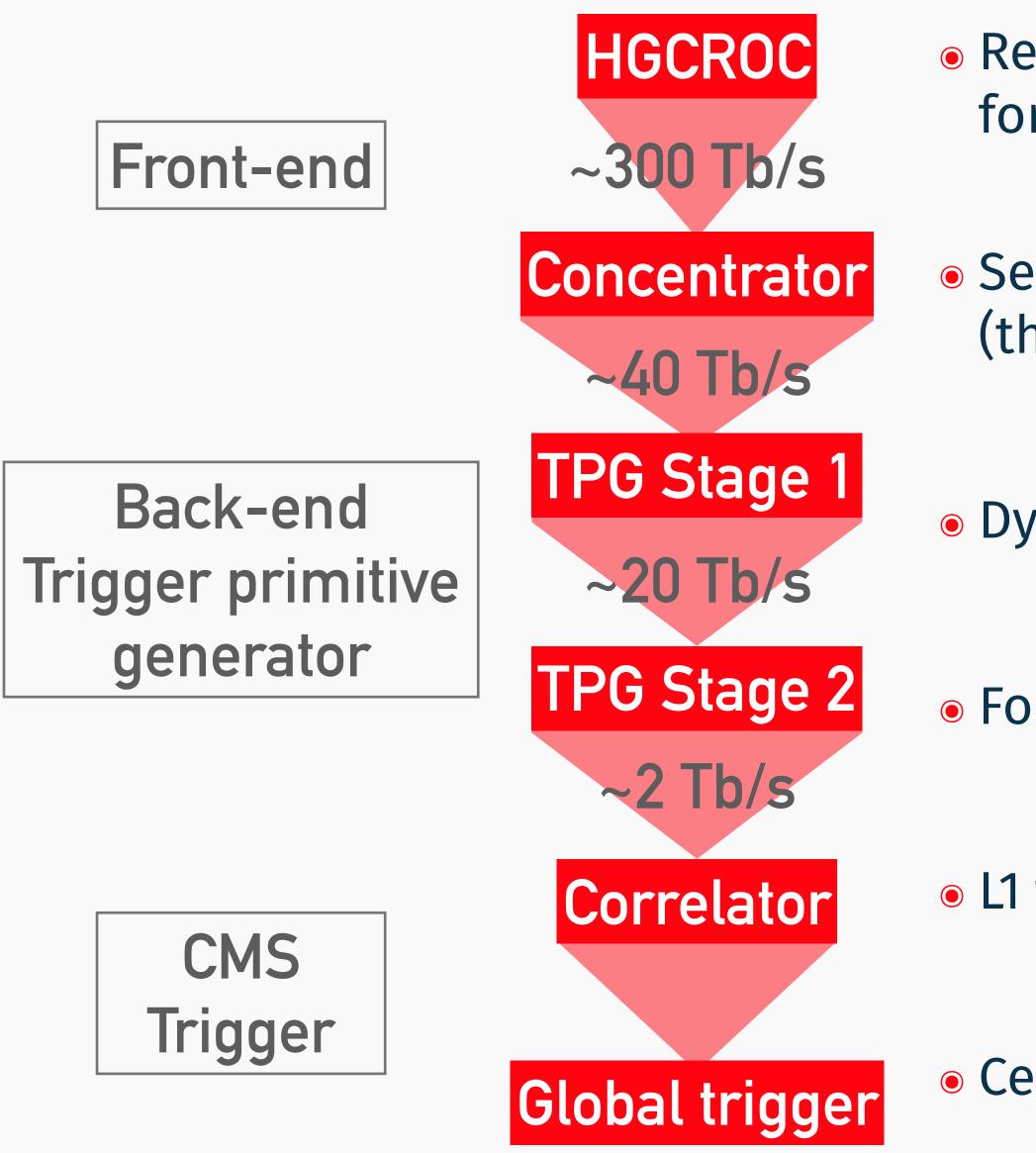






### **HGCAL TRIGGER FLOW**

CMS





- Resolution and granularity reduction, formation of trigger cells (TC)
- Selects fraction of trigger cells (threshold or fixed number of highest energy TC)
- Dynamical 2D clustering of trigger cells per layer
- Formation of 3D clusters trigger primitives (TP)
- L1 trigger correlator with input from track trigger
- Central CMS L1 trigger



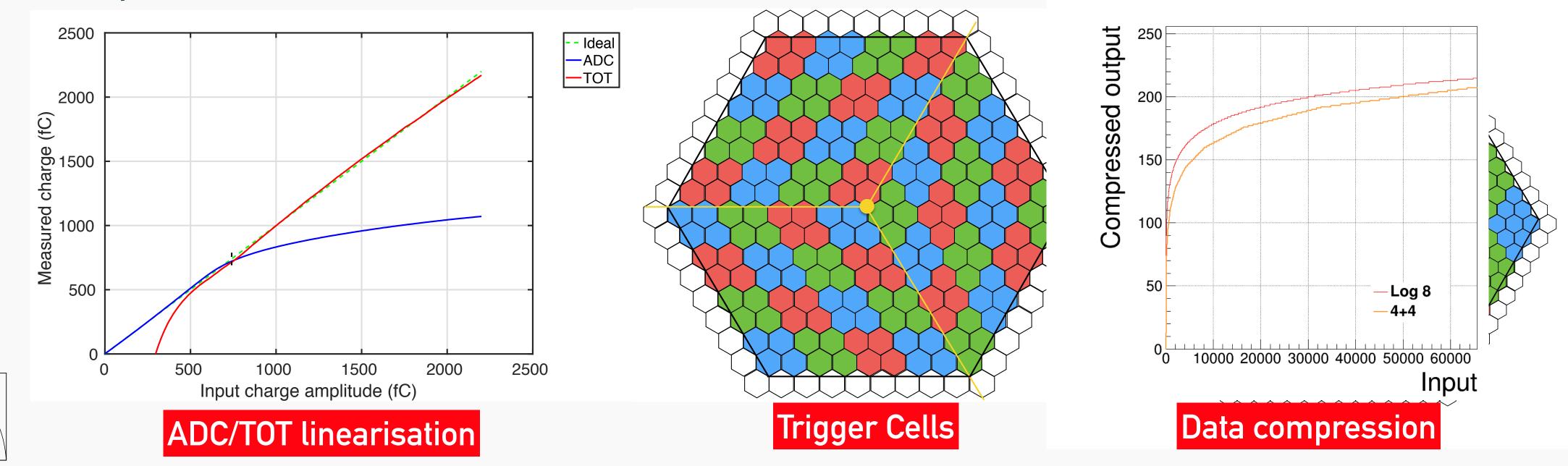
### **TRIGGER: HGCROCv1**

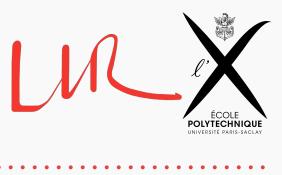
Reduced energy resolution:

- ADC/TOT linearization: automatic switching
- Digitized charge data:

CMS

- Gain: 11-bit ADC  $\rightarrow$  LSB @ 0.1 fC
- TOT: 12-bit TDC → LSB @ 2.5 fC
- Compensate LSB ratio (~25)  $\rightarrow$  17 bits





### • Reduced granularity:

- 4 (9) cells per Trigger Cell (48 per wafer)
- Sum of 4 channels  $\rightarrow$  17+2 bits
- Compression:
  - 4+4 encoding  $\rightarrow$  8 bits





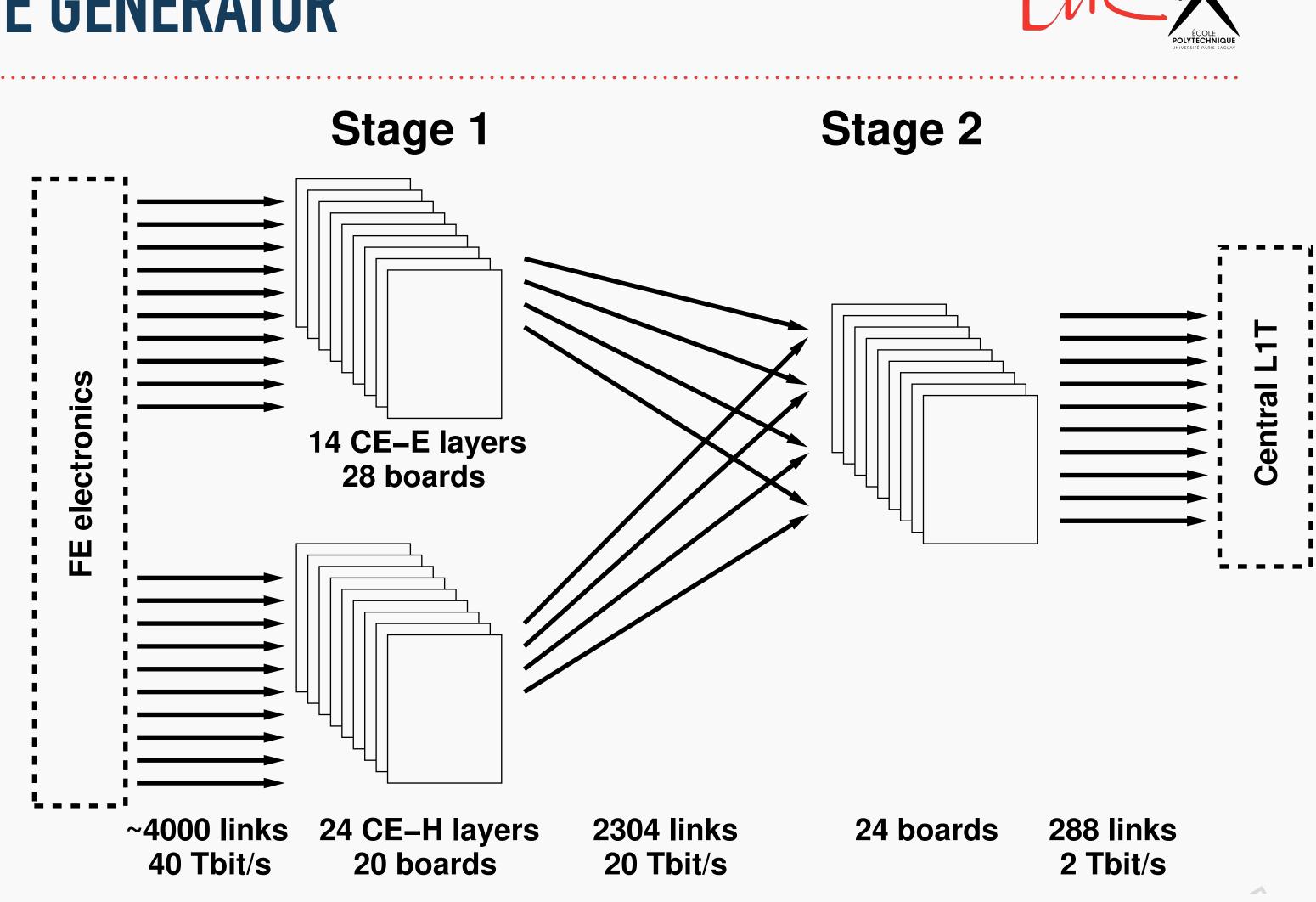
## **BACK-END: TRIGGER PRIMITIVE GENERATOR**

### • Stage 1:

 Dynamical clustering based on the Nearest Neighbour TCs generates **2D clusters** in each trigger layer

• Stage 2:

• Creation of **3D-clusters** exploiting the longitudinal development of the shower using the projected position of each 2D cluster to identify its direction

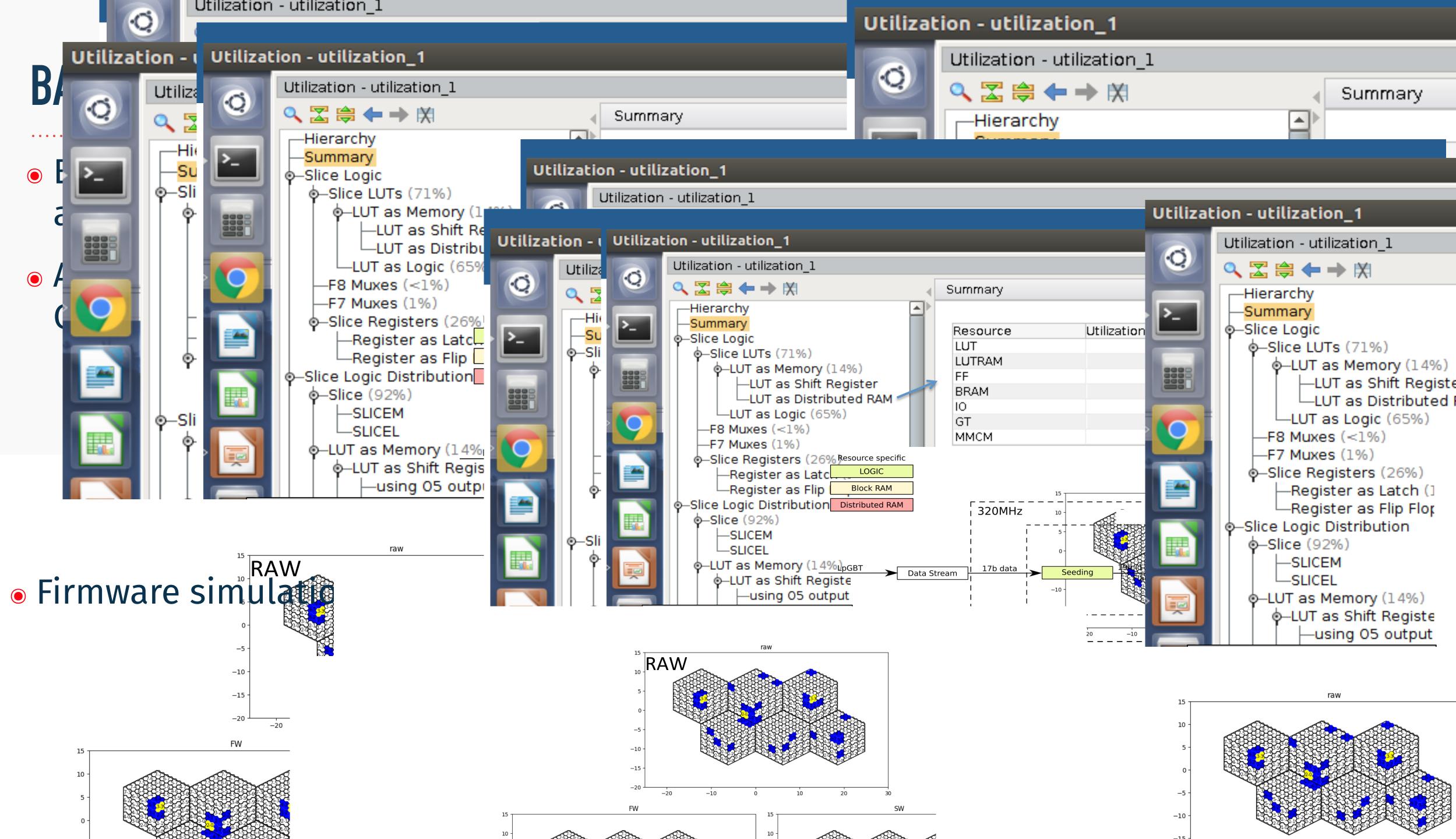




• The Stage 1 -> Stage 2 data transmission is x24 time-multiplexed in order for all data from one endcap to be processed by one single FPGA







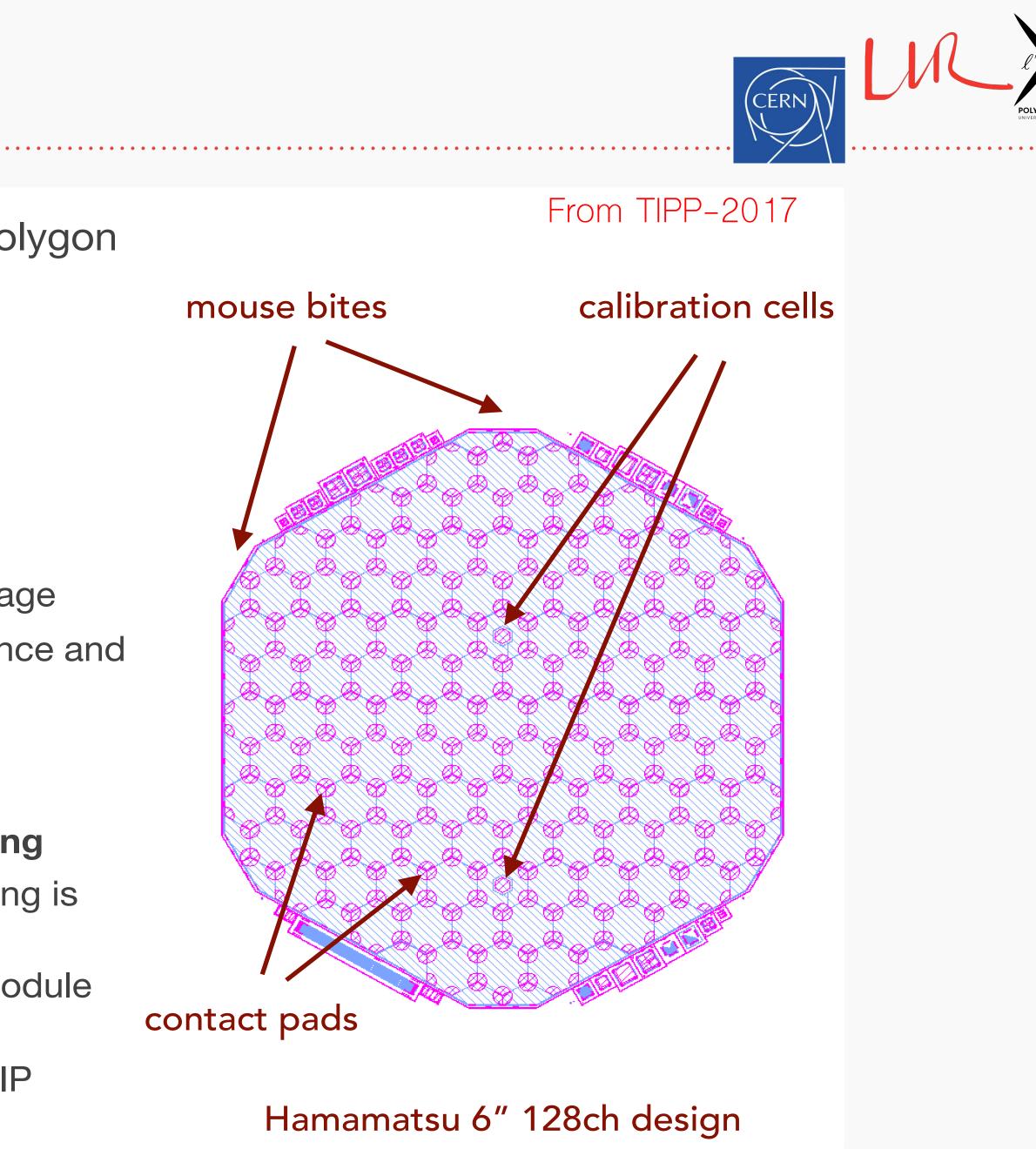
15 T

## HGCSS SI-SENSOR AND WAFERS

### • Hexagonal geometry as largest tile-able polygon

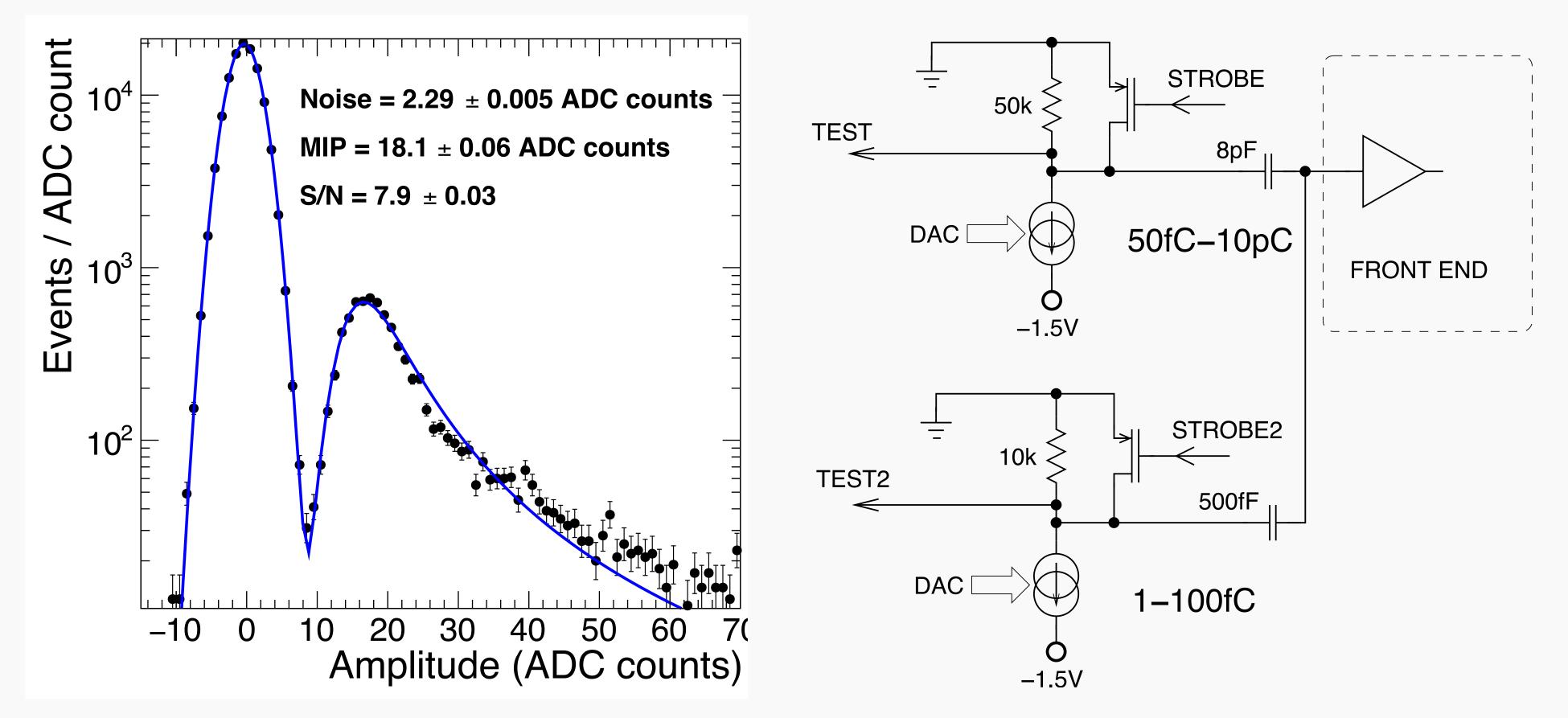
- 6" and 8" sensors considered
- Cell sizes of ~0.5 cm<sup>2</sup> and ~1 cm<sup>2</sup>
- Cell capacitance of ~50 pF
- Will most likely need n-on-p for inner layers
- Some design goals
  - 1kV sustainability to mitigate radiation damage
  - Four quadrants to study inter-cell gap distance and its influence on V<sub>bd</sub>, C<sub>int</sub> and CCE
- A few more details about those sensors
  - Active thickness by deep diffusion or thinning
  - Inner guard ring is grounded, outer guard ring is floating
  - Truncated tips, so called mouse bites, for module mounting
  - Calibration cells of smaller size for single MIP sensitivity at end of life







### **HGCAL CALIBRATION**



• MIP calibration for the absolute calibration of the ADC

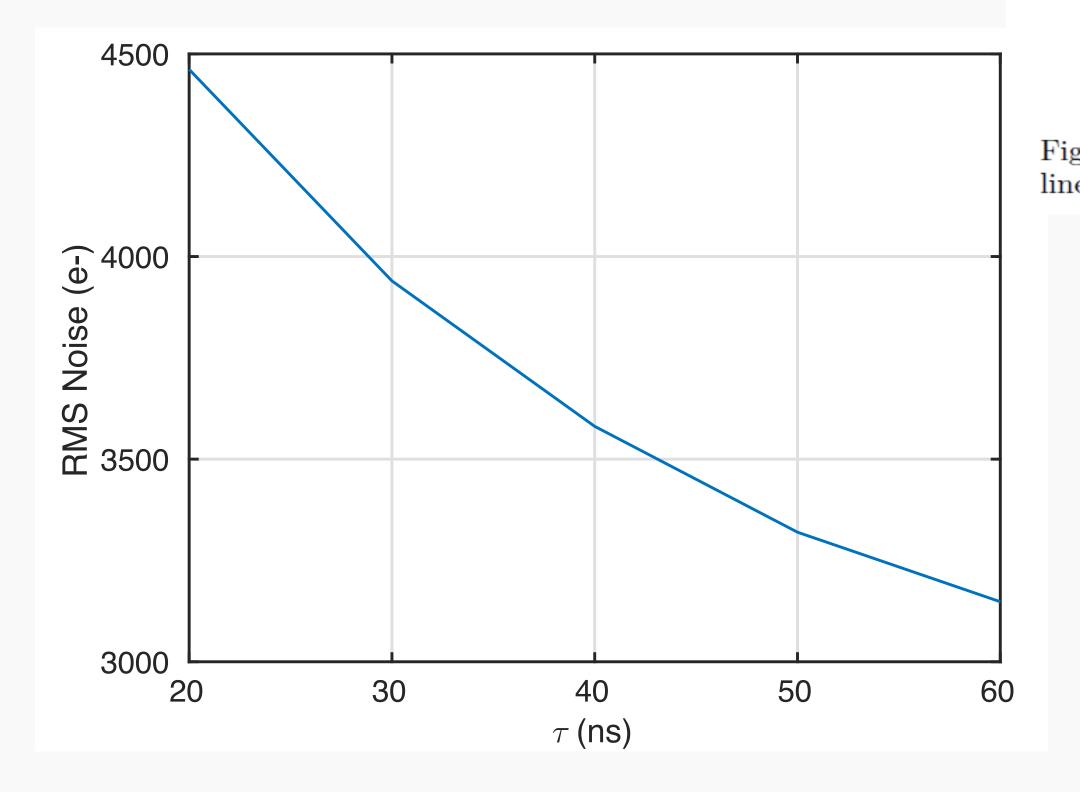
• A charge injection circuit with a large dynamic range will be used for covering both the ADC and TOT ranges





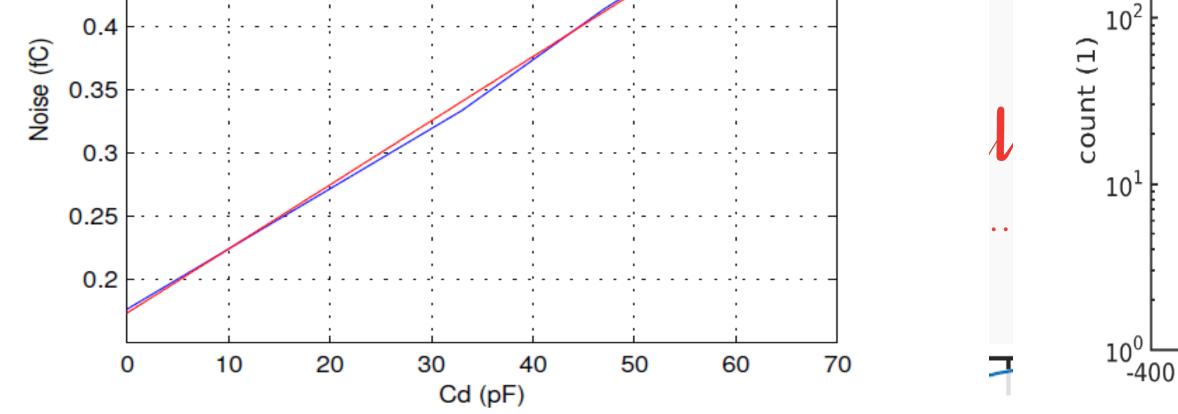


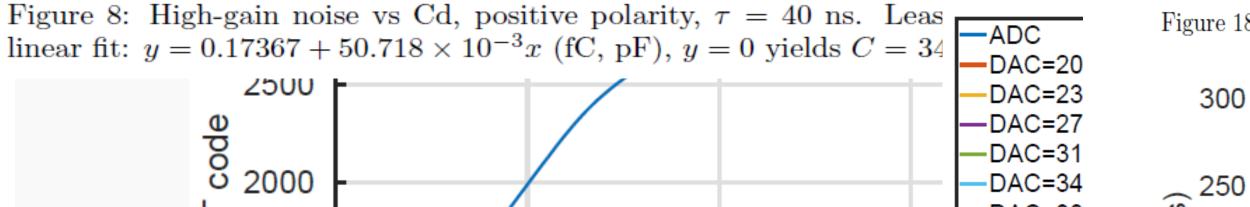


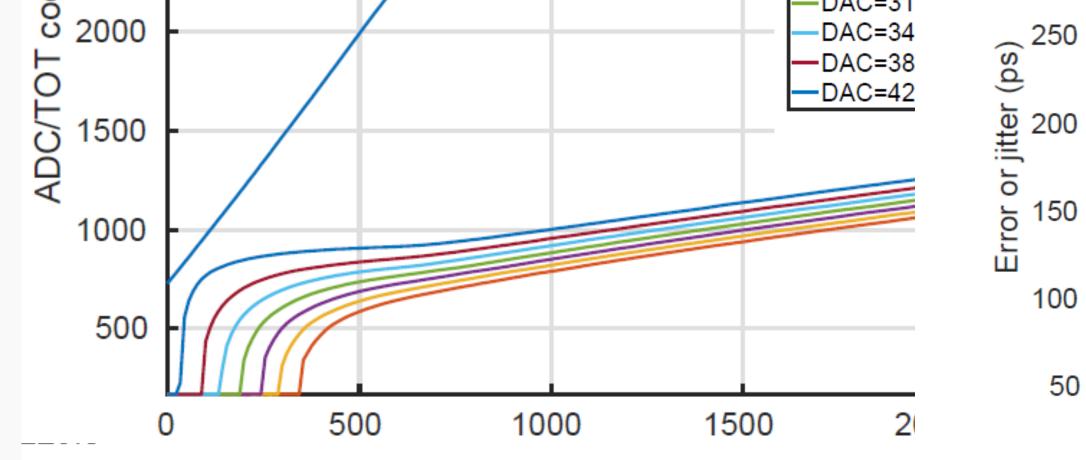


• Measurements from the SKIROC2\_CMS currently used for HGCAL testbeams • Highlights the increasing difficulty of achieving good noise performance at

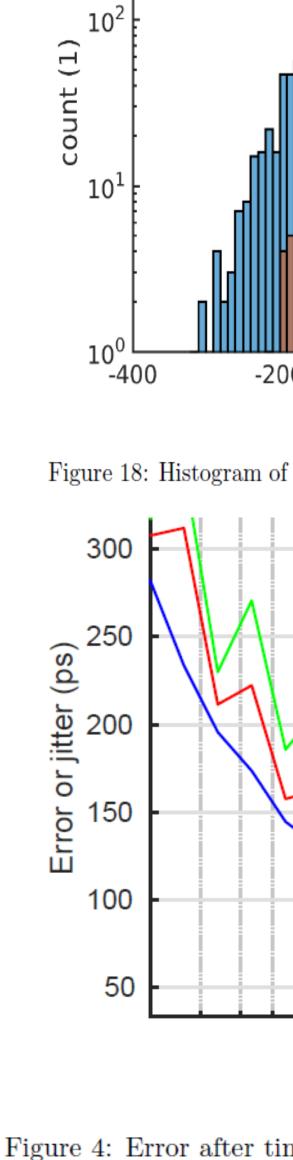
- CMS
- short shaping time





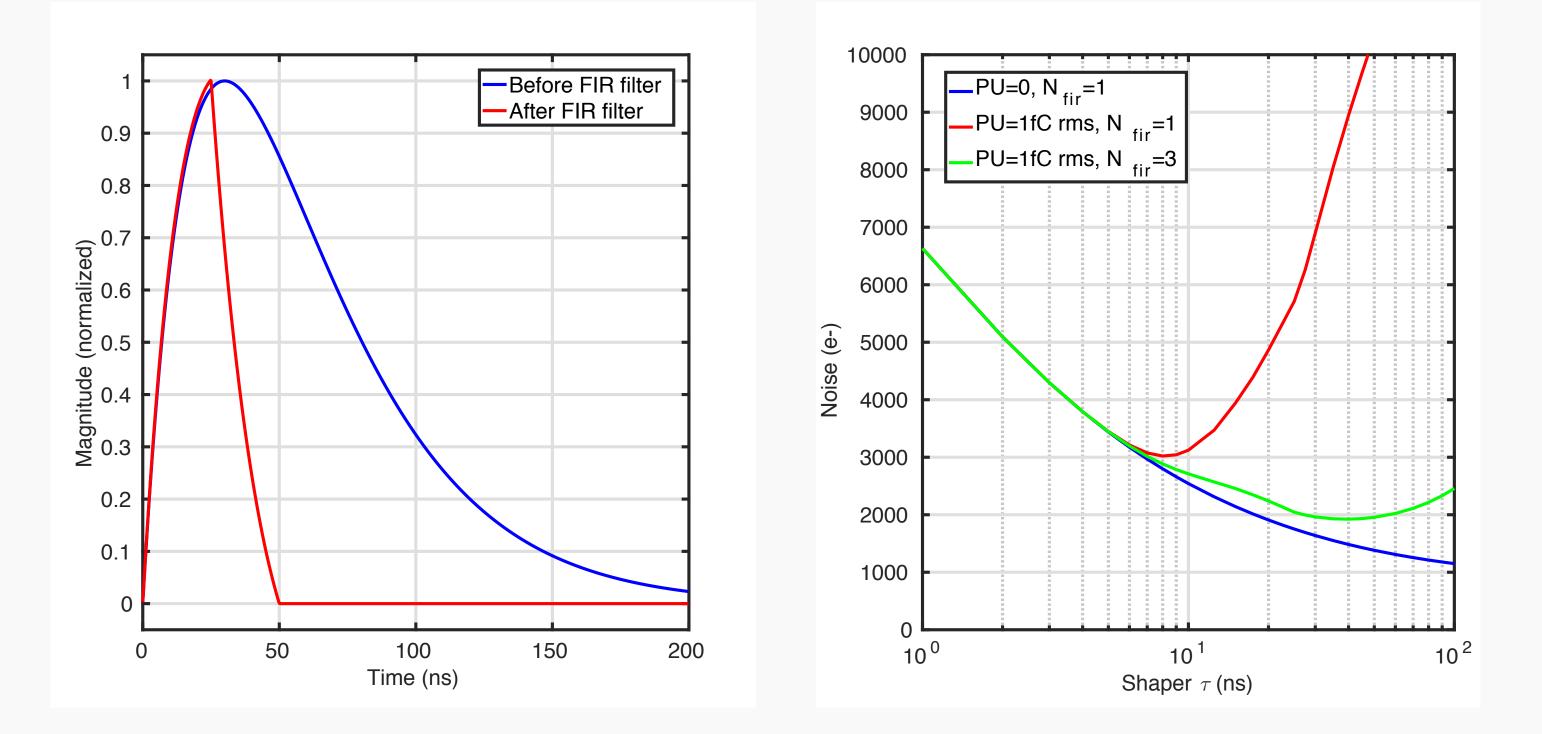


surement jitter of uncorr



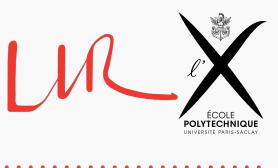


### Using FIR filters to manage occupancy



- high occupancy
- with and without 1 fC (6250 e-) pileup noise in preceding samples





2. 3-coefficient analog or digital finite impulse response (FIR) filters can help managing the

Simulated for  $e_n=0.5$  nV/ $\sqrt{Hz}$ ,  $C_d=80$  pF, 10-bit signal to noise ratio after the preamplifier,



## **CONCENTRATOR ASIC**

